



Republic of Tunisia  
Ministry of Higher Education  
and Scientific Research  
University of Carthage  
National Engineering School of Carthage



## SUMMER INTERNSHIP PROJECT REPORT

By

**Youssef HASNAOUI**

---

# Running Coremark on STM32 devices using Csolution project structure

---

Professional supervisor:

**Mohamed HAMROUNI**

Project Elaborated Within STMicroelectronics





# Dedications

*I dedicate this work to my family and friends.*

*To my mother **Monia Sellami**, your love and support means so much  
to me in every step of my journey. You're the best.*

*To my father **Makram Hasnaoui**, thank you so much for all the  
sacrifices you've made for my sake. I could never be here without you.*

*To my sister **Aicha**, your kindness and your belief in me have been a  
constant source of inspiration, and for that, I am very grateful.*

*To my friends, you have my most sincere gratitude for your support,  
your guidance and your company throughout this journey.*

Thank you,

Youssef HASNAOUI

# Acknowledgements

*I would like to sincerely thank everyone who had a hand in the development of this project.*

*Firstly, I want to express my utmost appreciation to **Mohamed HAMROUNI**, his guidance and support has been invaluable, and has kept me motivated and determined to give my best effort.*

*Last but not least, to every single person that contributed to the successful completion of this project with their constant support and motivation, you have my utmost thanks.*

# Contents

<b>Introduction</b>	<b>1</b>
<b>1 Internship Context</b>	<b>2</b>
1.1 Host Organization . . . . .	3
1.1.1 STMicroelectronics . . . . .	3
1.1.2 Activity Sectors . . . . .	3
1.1.3 Global Presence . . . . .	4
1.1.4 ST Tunis . . . . .	4
1.1.5 ST Support Solutions . . . . .	5
1.2 Project Context . . . . .	5
1.3 Problem Statement . . . . .	6
1.4 State of the Art . . . . .	6
1.5 Critique of Current State of the Art . . . . .	7
1.6 Proposed Solution . . . . .	7
1.7 Objective . . . . .	8
1.8 Conclusion . . . . .	8
<b>2 Theory and Key Concepts</b>	<b>9</b>
2.1 STM32 Microcontrollers (MCUs) . . . . .	10
2.1.1 STM32 Series . . . . .	10
2.1.2 ARM Cortex-M . . . . .	10
2.1.3 STM32 UART Peripheral . . . . .	10
2.1.4 STM32Cube Firmware Package . . . . .	11
2.2 Benchmarking . . . . .	11
2.2.1 Overview . . . . .	11
2.2.2 Benchmarking Microcontrollers . . . . .	12
2.2.3 Coremark . . . . .	13
2.3 C/C++ Build Process . . . . .	15
2.3.1 Compilation Toolchain . . . . .	15
2.3.2 Embedded Systems Toolchains . . . . .	16
2.3.3 Build Runners . . . . .	16
2.3.4 CMake . . . . .	17

---

2.4	Open-CMSIS-Pack . . . . .	17
2.4.1	CMSIS-Packs . . . . .	17
2.4.2	CMSIS-Toolbox . . . . .	19
2.5	Project Generation . . . . .	22
2.5.1	Regular Expressions: . . . . .	22
2.5.2	Templates & File Manipulation . . . . .	23
2.5.3	CMSIS-Toolbox Generators . . . . .	24
2.6	Loading And Debugging . . . . .	26
2.6.1	PyOCD . . . . .	26
2.6.2	STM32CubeProgrammer . . . . .	27
<b>3</b>	<b>Objectives Specification and Work Environment</b>	<b>28</b>
3.1	Project Specification . . . . .	29
3.1.1	Functional Requirements . . . . .	29
3.1.2	Non-Functional Requirements . . . . .	29
3.2	Structural Decisions . . . . .	30
3.2.1	CoreMark Project . . . . .	30
3.2.2	Project Generation Tool . . . . .	31
3.3	Use-Case Diagram . . . . .	32
3.4	Work Environment . . . . .	34
3.4.1	Hardware Resources . . . . .	34
3.4.2	Software Resources . . . . .	37
<b>4</b>	<b>Solution Implementation</b>	<b>40</b>
4.1	Demo Overview . . . . .	41
4.2	Sequence Diagram . . . . .	43
4.3	Demonstration Details and Explanation . . . . .	44
4.3.1	ECDSA Key Pair Generation . . . . .	44
4.3.2	ECDH Key Pair Generation . . . . .	48
4.3.3	ECDSA Signature Generation . . . . .	49
4.3.4	ECDSA Public Key and Signature Exchange . . . . .	51
4.3.5	ECDSA Signature Verification . . . . .	52
4.3.6	ECDH Public Key Exchange . . . . .	54
4.3.7	ECDH Shared Secret Generation . . . . .	54
4.3.8	AES GCM Key and IV Derivation . . . . .	55

4.3.9 AES GCM Symmetric Encryption . . . . .	56
4.3.10 Message Decryption and Tag Verification . . . . .	57
<b>Annexes</b>	<b>59</b>
Annexe 1. Exemple d'annexe . . . . .	59
Annexe 2. Entreprise . . . . .	60

# List of Figures

1.1	STMicroelectronics Activity Sectors . . . . .	3
1.2	STMicroelectronics Worldwide Presence . . . . .	4
1.3	STMicroelectronics Tunis . . . . .	5
2.1	Distribution of control instructions and mispredictions over CoreMark execution. . . . .	14
2.2	Compilation Process Diagram . . . . .	15
2.3	Software Packs Types . . . . .	17
2.4	Software Component Interface . . . . .	19
2.5	Csolution Operation . . . . .	20
2.6	Cbuild Workflow . . . . .	21
2.7	Templating Process . . . . .	24
2.8	Generator Integration in CMSIS-Toolbox . . . . .	25
2.9	PyOCD Running and Debugging Workflow . . . . .	26
3.1	Project Generation Tool Architecture . . . . .	32
3.2	Automated CoreMark Benchmarking Use-Case Diagram . . . . .	32
3.3	STM32 Microcontroller Portfolio . . . . .	34
3.4	IAR Embedded Workbench . . . . .	38
3.5	STM32CubeMX . . . . .	39
4.1	Sequence Diagram for "CryptoEngine" Demo . . . . .	43
4.2	PKA ECC Fp Scalar Multiplication . . . . .	45
4.3	Code Implementation of NIST P-256 Parameters . . . . .	46
4.4	HAL PKA ECC Input Structure . . . . .	47
4.5	PKA ECC Setup . . . . .	47
4.6	ECDSA Private Key . . . . .	47
4.7	ECDSA Public Key Generation Function . . . . .	48
4.8	Generated ECDSA Public Key . . . . .	48
4.9	ECDH Private Key . . . . .	48
4.10	ECDH Public Key Generation Function . . . . .	49
4.11	Generated ECDH Public Key . . . . .	49
4.12	ECDSA Sign Operation . . . . .	49

4.13 HAL PKA ECDSA Input Structure . . . . .	50
4.14 HAL PKA ECDSA Input Structure . . . . .	50
4.15 ECDSA Integer "K" . . . . .	50
4.16 ECDSA Signing Function . . . . .	51
4.17 Generated ECDSA Signature . . . . .	51
4.18 Received ECDSA Signature . . . . .	52
4.19 PKA "ECDSA Verification" Mode . . . . .	52
4.20 ECDSA Verification Function . . . . .	53
4.21 Successful ECDSA Signature Verification . . . . .	53
4.22 Failed ECDSA Signature Verification . . . . .	54
4.23 Received ECDH Public Key . . . . .	54
4.24 ECDH Shared Secret Generation Function . . . . .	55
4.25 ECDH Shared Secret . . . . .	55
4.26 AES HAL Structure . . . . .	56
4.27 AES Structure Initialization . . . . .	56
4.28 AES GCM Key and Initialization Vector Derivation . . . . .	57
4.29 AES GCM Key and Initialization Vector Derivation . . . . .	57
4.30 Message Decryption Output . . . . .	58
Annexe 2.1 Logo d'entreprise . . . . .	60

# List of Tables

1.1	Comparison of Approaches for Embedded Benchmarking and Automation . . . . .	7
3.1	Functional Requirements for CMSIS-Toolbox based automated benchmarking . . . . .	29
3.2	CoreMark Project Structure . . . . .	31
3.3	Project Generation Tool Structure . . . . .	32
3.4	Automated CoreMark Benchmarking . . . . .	33
3.5	STM32 Microcontroller Families . . . . .	35
4.1	Steps for "CryptoEngine" Demo . . . . .	41
4.2	NIST P-256 Curve Specifications . . . . .	45
	Annexe 1.1 Exemple tableau dans l'annexe . . . . .	59

# List of Acronyms

- **API** = Application Programming Interface
- **ARM** = Advanced RISC Machine
- **BRE** = Basic Regular Expression
- **BSP** = Board Support Pack
- **CLI** = Command-Line Interface
- **CMSIS** = Cortex Microcontroller Software Interface Standard
- **DFP** = Device Family Pack
- **DRAM** = Dynamic Random Access Memory
- **DWARF** = Debugging With Attributed Record Formats
- **ELF** = Executable and Linkable Format
- **ERE** = Extended Regular Expression
- **FPU** = Floating Point Unit
- **GCC** = GNU Compiler Collection

- **GNU** = GNU's Not Unix
- **GUI** = Graphical User Interface
- **HAL** = Hardware Abstraction Layer
- **I/O** = Input/Output
- **IAR** = Ingenjörsfirma Anders Rundgren
- **IDE** = Integrated Developement Environment
- **IEEE** = Institute of Electrical and Electronics Engineers
- **IP** = Integrated Peripheral
- **IV** = Initialization Vector
- **JSON** = JavaScript Object Notation
- **LL** = Low-Layer
- **LLVM** = Low Level Virtual Machine
- **MCU** = Micro Controller Unit
- **OCD** = On-Chip Debugger

- **PLM** = Project Lifetime Management
- **POSIX** = Portable Operating System Interface
- **RAM** = Random Access Memory
- **ROM** = Read-Only Memory
- **RTE** = RunTime Environment
- **RTOS** = Real-Time Operating System
- **RegEx** = Regular Expression
- **SCVD** = Software Component Viewer Description
- **SDRAM** = Synchronous Dynamic Random Access Memory
- **SRAM** = Static Random Access Memory
- **SRE** = Simple Regular Expression
- **SVD** = System View Description
- **UART** = Universal Asynchronous Receiver Transmitter
- **USART** = Universal Synchronous Asynchronous Receiver Transmitter
- **YAML** = Yet Another Markup Language

# Introduction

In today's technological landscape, the importance of benchmarking in embedded systems cannot be overstated. Embedded systems are integral to a wide range of applications, from consumer electronics and industrial automation to healthcare devices and automotive systems. Therefore, evaluations provide objective data on performance, efficiency and reliability, making them essential for making informed design and purchasing decisions. As systems grow more complex and interconnected, the number of configurable parameters and potential performance bottlenecks expands, increasing the risk of suboptimal performance, wasted resources and failed deployments. Establishing a rigorous and standardized benchmarking methodology is therefore paramount to ensure systems meet their intended requirements and deliver value in both development and production environments.

Benchmarking provides the fundamental framework for this objective analysis by establishing a standardized set of metrics and tests to quantify a system's performance. Effective benchmarking allows developers to measure key characteristics such as processing speed, memory throughput, power consumption, and real-time task execution, creating a data-driven basis for comparison. However, executing benchmarks in embedded systems comes with challenges. Developers must navigate complexities such as isolating the unit under test, minimizing the influence of external systems, selecting appropriate tools, and ensuring that the test conditions are consistent and reproducible across different platforms and devices. Inaccurate methodology or poorly designed tests can cause misleading results, rendering the data useless for making decisions.

The dependency on proprietary and platform-specific vendor tools can lock projects into a single ecosystem and hinder reproducibility. There is a growing need to have development environments that prioritize portability and vendor independence, allowing benchmarks to be built, deployed, and executed consistently across a wide range of hardware. By abstracting away toolchain-specific complexities, such environments allow developers to focus on the benchmark results themselves rather than the intricacies of the different build processes.

This report explores the implementation of the CoreMark benchmark on STM32 devices using CMSIS-Toolbox, and the related Csolution project structure as a step towards this goal. This method demonstrates a move away from proprietary IDE-bound setups and towards a portable, platform-independent driven workflow. By leveraging a toolchain-agnostic approach, we establish a reproducible environment for evaluations. This reduces vendor lock-in, enhances cross-platform compatibility, ensures the data is a reliable reflection of the hardware capabilities, and, as a side effect, allows for a fair comparison between the available toolchains.

# INTERNSHIP CONTEXT

---

## Contents

<b>1</b>	<b>Host Organization . . . . .</b>	<b>3</b>
<b>2</b>	<b>Project Context . . . . .</b>	<b>5</b>
<b>3</b>	<b>Problem Statement . . . . .</b>	<b>6</b>
<b>4</b>	<b>State of the Art . . . . .</b>	<b>6</b>
<b>5</b>	<b>Critique of Current State of the Art . . . . .</b>	<b>7</b>
<b>6</b>	<b>Proposed Solution . . . . .</b>	<b>7</b>
<b>7</b>	<b>Objective . . . . .</b>	<b>8</b>
<b>8</b>	<b>Conclusion . . . . .</b>	<b>8</b>

## Internship Context

This opening chapter focuses on introducing the host company STMicroelectronics, and provides an overview of the company's activities and global presence. It also includes an introduction to ST Tunis and the Support Solutions team, which played a pivotal role in the execution of this project, as well as an outline of the project's overall framework. Following the presentation of the challenges, we will explore the current state of the art and finally present the proposed solution which is the main objective of this project.

### 1.1 Host Organization

#### 1.1.1 STMicroelectronics

STMicroelectronics (ST) is a global leader in the semiconductor industry, providing innovative solutions across various markets, including automotive, industrial, personal electronics, and communications equipment.

Founded in 1987 through the merger of SGS Microelettronica of Italy and Thomson Semiconducteurs of France, ST has grown to become one of the largest semiconductor companies in the world.

#### 1.1.2 Activity Sectors

ST's mission is to be the undisputed leader in the semiconductor market, delivering sustainable and innovative solutions that make a positive impact on people's lives. The company's vision is to create technology that enables a more intelligent and connected world, driving progress in key areas such as smart driving, smart industry, smart home, and smart city applications.

The following illustration highlights the key end markets targetted by ST's solutions [1].

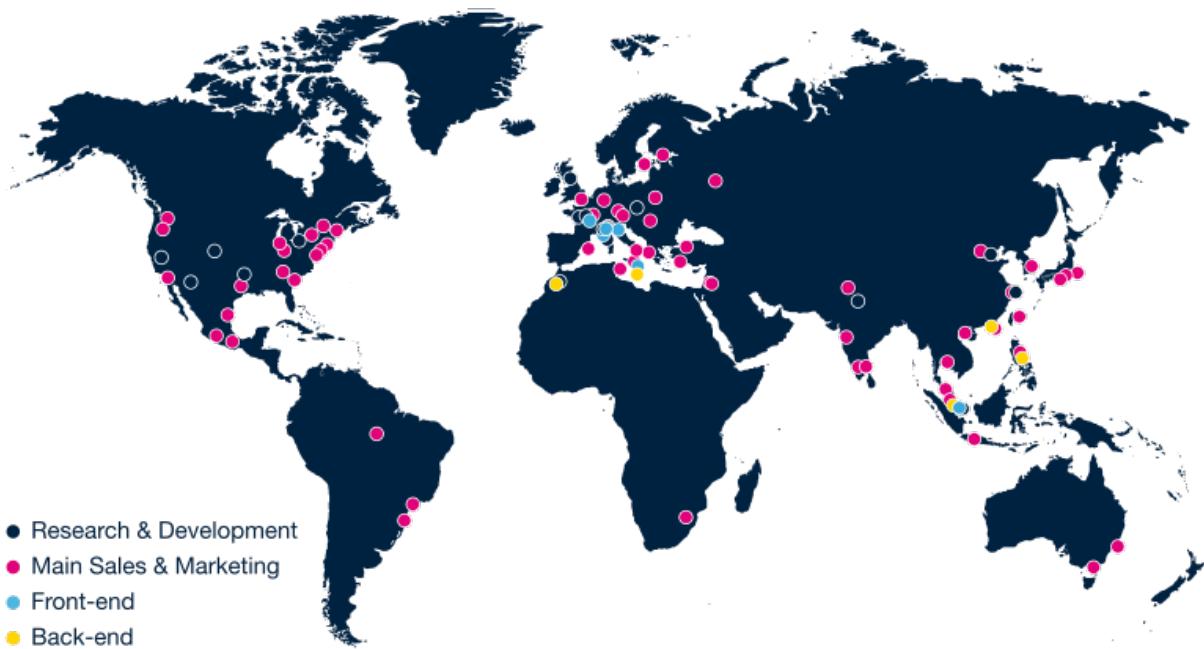


**Figure 1.1:** STMicroelectronics Activity Sectors

### 1.1.3 Global Presence

STMicroelectronics operates in more than 35 countries, with a strong presence in key markets around the world. Figure 1.2 illustrates the company's global network, which includes [1]:

- **Manufacturing Sites:** ST has 14 main manufacturing sites, strategically located to serve its global customer base efficiently.
- **Sales & Marketing Offices:** With a network of sales and marketing offices, ST provides localized support and services to its customers.
- **R&D Centers:** ST's R&D centers are spread across the globe, fostering innovation and collaboration.



**Figure 1.2:** STMicroelectronics Worldwide Presence

### 1.1.4 ST Tunis

The STMicroelectronics Tunis site, located in the El Ghazela Technopark, employs over 100 professionals in various fields such as tools, applications, quality, and support functions. The facility is involved in all stages of the microelectronics industry, from initial circuit design to final verification before mass production.

With expertise in both hardware and software, the Tunis center's activities include electronic circuit design, software tool development, application software support, and the electrical validation and verification of new circuits. This diverse skill set allows the center to contribute significantly to ST's global operations.



**Figure 1.3:** STMicroelectronics Tunis

### 1.1.5 ST Support Solutions

The ST Support Solutions team is dedicated to delivering comprehensive customer support while managing and publishing STM32 product documentation. Their role includes providing in-depth technical support for ST's tools and products, helping customers troubleshoot problems and optimize their use of these technologies. They ensure the accuracy, clarity, and consistency of all technical documentation, which is regularly updated to reflect the latest developments and innovations. The team is also involved in enhancing and maintaining existing products, as well as defining new products, derivatives, and application references to meet evolving market needs. Additionally, they lead initiatives related to intellectual property applications, offering specific support through the development of application notes, training programs, and other resources that help customers fully understand and utilize ST's products. This multifaceted approach ensures both customer satisfaction and continuous improvement in the STM32 ecosystem.

## 1.2 Project Context

Benchmarking microcontrollers is a fundamental step in evaluating their computational capabilities, power efficiency, and suitability for various applications, such as IoT, robotics, or industrial control. Among the many available benchmarks, CoreMark, developed by EEMBC, has become the de facto standard for embedded systems because it provides a well-defined, portable, and reliable performance metric. STM32 microcontrollers, are widely adopted in the embedded systems industry due to their scalability, rich peripheral set, and performance-to-cost ratio.

The **CMSIS** initiative, led by Arm, and its Open-CMSIS-Pack ecosystem aim to standardize microcontroller development workflows. Within this ecosystem, Csolution provides a modern, metadata-driven project structure

that enables cross-platform builds, device abstraction, and automation. Leveraging Csolution can significantly simplify benchmarking workflows by providing a unified and reproducible project generation and build process.

### 1.3 Problem Statement

Running CoreMark on STM32 devices traditionally requires manual setup for each device, including:

- Creating and configuring individual projects for different STM32 families.
- Managing peripheral initialization.
- Providing a clock source to Coremark.
- Handling different compiler options and toolchains.
- Customizing linker scripts manually.
- Maintaining multiple project files for IDEs like Keil µVision, IAR EWARM, or others.

This manual process is time-consuming, error-prone, and non-scalable, especially when benchmarking a wide range of devices. There is currently no standardized, automated workflow that allows developers to quickly generate CoreMark-ready projects for different STM32 targets while ensuring consistency and portability.

### 1.4 State of the Art

The current approaches to running benchmarks on STM32 devices typically rely on:

- **Vendor-Specific IDEs:** IDEs provide an easy way to manage projects via a graphical interface, they typically provide tools for peripheral configuration, memory management and compiler options. They also offer integrated build and debug environments.
- **Standalone CoreMark Implementations:** EEMBC provides CoreMark source code with minimal reference implementations, it is up to the developer to manually adapt it to the target device, providing startup and initialization code, memory configuration and a clock source.
- **Custom Build Systems:** Some environments require the use of custom build systems such as CMake and Make, these tools allow the developer to manually manage dependencies, defines and other C/C++ related build configuration.
- **CMSIS Packs:** CMSIS packs offer a standardized way of packaging drivers, middleware and device specific files, they provide metadata to describe the device's memory and peripheral layout.

## 1.5 Critique of Current State of the Art

While the above methods work, they exhibit several limitations:

**Table 1.1:** Comparison of Approaches for Embedded Benchmarking and Automation

Approach	Advantages	Limitations
<b>Vendor-Specific IDEs</b>	Intuitive GUI, built-in drivers, easy to use	Projects are IDE-specific, hard to automate, poor scalability
<b>Standalone CoreMark</b>	Portable reference code on computers	Significant manual effort for adaptation to each MCU
<b>Custom Build Systems</b>	Flexible, automation-friendly	Requires deep expertise, no standardized metadata integration
<b>CMSIS Packs</b>	Standardized packaging and metadata support	Lack seamless integration with benchmarking and automation

## 1.6 Proposed Solution

The proposed solution centers around the aspects of automation and standardization, leveraging the **CMSIS Solution project structure**, part of the **Open-CMSIS-Pack** ecosystem in order to achieve the desired outcome.

The key aspects of the solution are:

- **Unified Project structure** By making use of the csolution project files `*.csolution.yml`, `*.cproject.yml` etc..., we can describe build configuration, dependencies, and device parameters in a centralized way, simplifying maintenance and reuse.
- **Automating Project Generation** While the **Csolution project structure** offers a standardized way of configuring projects, the source code of the application has to be managed somehow, although generators like **STM32CubeMX** does a decent job of generating peripheral configuration, it is still slow and GUI based, so it can't be used in a fully automated manner. Therefore, we can make use of creating a tool to handle automating source code and linker script generation, device configuration and even generating the csolution project files.
- **Portable and Cross-Toolchain Support** Allow the project to be compiled through the main toolchains used in embedded applications, through **CMSIS-Toolbox**, as well as ensuring the project can be built and debugged in multiple IDE environments.
- **CoreMark Integration** Embed the **CoreMark** source code into the standardized generation template, making it easily portable amongst **all STM32** MCU targets.

## 1.7 Objective

The main objective of this project is to develop a standardized, automated workflow for running CoreMark on STM32 devices using the Csolution project structure.

## 1.8 Conclusion

Benchmarking embedded systems is essential for performance evaluation and hardware selection. However, the current manual approaches to running CoreMark on STM32 devices are inefficient, inconsistent, and hard to scale.

This project addresses these challenges by introducing a Csolution-based workflow that integrates device metadata, automation, and portable build configurations. By leveraging the Open-CMSIS-Pack ecosystem, the proposed solution provides a unified, reproducible, and scalable benchmarking framework.

The outcome is a streamlined process where CoreMark can be quickly deployed to any STM32 target, results can be gathered reliably, and the entire workflow can serve as a foundation for future benchmarking or performance evaluation tasks across diverse embedded platforms.

# THEORY AND KEY CONCEPTS

---

## Contents

<b>1</b>	<b>STM32 Microcontrollers (MCUs)</b>	<b>10</b>
<b>2</b>	<b>Benchmarking</b>	<b>11</b>
<b>3</b>	<b>C/C++ Build Process</b>	<b>15</b>
<b>4</b>	<b>Open-CMSIS-Pack</b>	<b>17</b>
<b>5</b>	<b>Project Generation</b>	<b>22</b>
<b>6</b>	<b>Loading And Debugging</b>	<b>26</b>

## Introduction

In this chapter, we will explore the key concepts essential to our project. We begin by introducing the STM32 ecosystem, providing an overview of its components and their functionalities. Following this, we delve into the theoretical aspects of benchmarking and embedded build systems relevant to our work. Finally, we will discuss the essentials of automating project generation.

### 2.1 STM32 Microcontrollers (MCUs)

#### 2.1.1 STM32 Series

STM32 microcontrollers (MCUs) are a family of 32-bit microcontrollers based on the ARM Cortex-M processor. Developed by STMicroelectronics, the STM32 series offers a wide range of products that cater to various applications, from simple embedded systems to complex industrial automation. The STM32 MCUs are categorized into several series, each designed to meet specific application requirements. Some of the most commonly used series are the **STM32F** series and the **STM32H** series. Within each series.

#### 2.1.2 ARM Cortex-M

The STM32 microcontrollers are built around the ARM Cortex-M cores, which are designed for efficient and high-performance processing in embedded systems. The ARM Cortex-M family includes several cores, such as Cortex-M0, Cortex-M4, Cortex-M7, and Cortex-M85, each offering different levels of performance and features.

STM32 MCUs are grouped into families, a combination of a series and an ARM Cortex-M core, the number proceeding the STM32 series indicates the core, for example, STM32H7 family indicates a microcontroller from the STM32H series with a Cortex-M7 core, while the STM32N6 family indicates a STM32N series microcontroller with a Cortex-M55 core.

#### 2.1.3 STM32 UART Peripheral

STM32 microcontrollers come with a rich set of integrated peripherals (IPs) that enhance their functionality and enable developers to build complex and feature-rich applications. The one of interest in this report is the UART peripheral. UART is a hardware protocol and communication interface that uses two wires for data exchanges between peripherals that do not share a common clock signal. It fits our use case of transmitting data from the microcontroller to the host computer in order to have access to Coremark results.

### 2.1.4 STM32Cube Firmware Package

The STM32Cube Firmware Package is a comprehensive software suite provided by STMicroelectronics to accelerate development on STM32 microcontrollers. Its components include but are not limited to:

- **CMSIS:** A vendor-independent standard defined by Arm that provides a consistent API for Cortex-M cores, STM32Cube Firmware provides an implementation of the CMSIS-Core layer, these include device and family specific header files, as well as templates for startup files and linker scripts.
- **HAL:** Simplifies peripheral configuration and access through high-level APIs, reducing development complexity and allows for re-usability across different hardware.
- **LL Drivers:** Provide fine-grained control of peripherals with minimal overhead, suitable for performance-critical applications.

Together, these components create an environment where developers can choose the appropriate level of abstraction based on their specific requirements, all while maintaining compatibility and code re-usability across the STM32 ecosystem.

## 2.2 Benchmarking

### 2.2.1 Overview

Benchmarking is the systematic process of evaluating and comparing the performance of a computing system, or a specific component within that system, by running a standardized set of tasks and synthetic workloads. The key aspects of benchmarks include:

- **Metrics:** Performance is measured using quantifiable units, Common metrics include:
  - **Throughput:** The amount of work done per unit of time (e.g., operations/second, frames/second, MB/s).
  - **Latency:** The time taken to complete a single operation (e.g., microseconds per operation).
  - **Power Efficiency:** Performance achieved per watt of power consumed (e.g., points per watt, inferences per joule).
  - **Memory Usage:** The amount of RAM or cache consumed during a task.

- **Benchmark Types:**

- **Synthetic Benchmarks:** These are specialized programs designed to stress specific subsystems like the CPU, memory, or GPU. They provide standardized but often abstract results.
- **Application Benchmarks:** Use real-world software and workloads (e.g., rendering a video file, compiling a large code-base, running a specific game at a set quality). These measure performance in practical, user-facing scenarios.
- **Micro-benchmarks:** Isolate and test a very specific, low-level operation (e.g., floating-point multiplication speed, memory access latency).

### 2.2.2 Benchmarking Microcontrollers

Although the same benchmarks can be run on most pieces of technology, the implementation differs slightly for microcontrollers. Computers can delegate tasks such as scheduling and printing to the underlying operating system, which is not the case when it comes to embedded devices. We have to take into account handling threads, I/O operations, memory regions, and code sections. This can make the implementation tricky at times. The following steps are necessary to ensure proper benchmarking on a microcontroller:

- **Clock Source Provision:** Benchmarks rely on CPU ticks in order to get an accurate estimate of the time taken to run the workloads, providing access to the tick counter, whether it be the internal System Clock or an external timer, as well as the frequency of said clock is crucial for proper measurements.
- **Print Logic Implementation:** Computers can offer multiple ways of getting data from a program, such as logging them into files or printing them to the standard output, this option is not available on microcontrollers, therefore, we have to provide our own mechanism of data transmission. In our context, the print logic was implemented to send data via the UART peripheral.
- **Code Execution Management:** For high-end systems relying on an operating system, the most common approach is to load the program from disk into volatile memory(RAM) and begin execution without any extra steps. However, in our case, we have to specify the regions of memory where each part of the program will reside, the most common types of memory are: FLASH, SRAM, ITCM/DTCM, SDRAM, NVMe, all of them can be either external or internal. Depending on multiple factors, such as wait-states, clock synchronization and the communication interface, the results can have vastly varying results depending on the chosen regions.

### 2.2.3 Coremark

There have been many attempts to provide a single number that can totally quantify the ability of a CPU. Be it MHz, MOPS, MFLOPS - all are simple to derive but misleading when looking at actual performance potential. EEMBC's CoreMark is a benchmark that measures the performance of microcontrollers (MCUs) and central processing units (CPUs) used in embedded systems. It is designed to run on devices from 8-bit microcontrollers to 64-bit microprocessors. CoreMark ties a performance indicator to execution of simple code, but rather than being entirely arbitrary and synthetic, the code for the benchmark uses basic data structures and algorithms that are common in practically any application

#### Coremark Composition

To appreciate the value of CoreMark, it's worthwhile to dissect its composition, which in general is comprised of lists, strings, and arrays (matrixes to be exact). Lists commonly exercise pointers and are also characterized by non-serial memory access patterns. In terms of testing the core of a CPU, list processing predominantly tests how fast data can be used to scan through the list. For lists larger than the CPU's available cache, list processing can also test the efficiency of cache and memory hierarchy.

##### 2.2.3.1 List Processing

List processing consists of reversing, searching or sorting the list according to different parameters, based on the contents of the list data items. In particular, each list item can either contain a pre-computed value or a directive to invoke a specific algorithm with specific data to provide a value during sorting. To verify correct operation, CoreMark performs a 16b cyclic redundancy check (CRC) based on the data contained in elements of the list. Since CRC is also a commonly used function in embedded applications, this calculation is included in the timed portion of the CoreMark.

##### 2.2.3.2 Matrix Processing

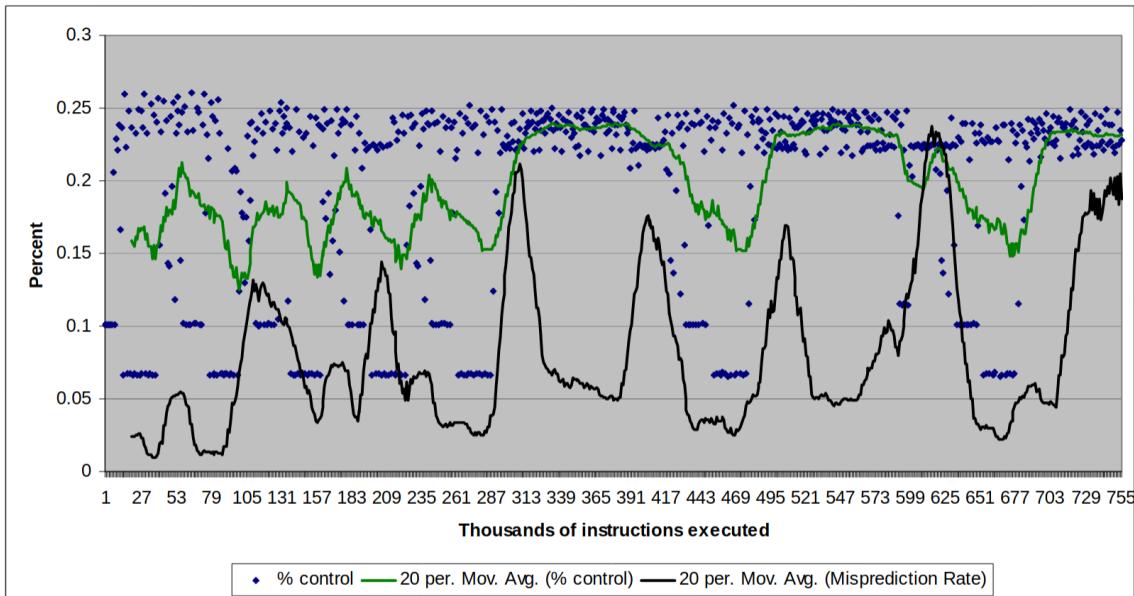
Many algorithms use matrixes and arrays, warranting significant research on optimizing this type of processing. These algorithms test the efficiency of tight loop operations as well as the ability of the CPU and associated toolchain to use ISA accelerators such as MAC units and SIMD instructions. These algorithms are composed of tight loops that iterate over the whole matrix. CoreMark performs simple operations on the input matrixes, including multiplication with a constant, a vector, or another matrix. CoreMark also tests operating on part of the data in the matrix in the form of extracting bits from each matrix item for operations. To validate that all operations have been performed, CoreMark again computes a CRC on the results from the matrix test.

### 2.2.3.3 State machine processing

An important function of a CPU core is the ability to handle control statements other than loops. A state machine based on switch or ‘if’ statements is an ideal candidate for testing that capability. There are 2 common methods for state machines – using switch statements or using a state transition table. Because CoreMark already utilizes the latter method in the list processing algorithm to test load/store behavior, CoreMark uses the former method, switch and ‘if’ statements, to exercise the CPU control structure. The state machine tests an input string to detect if the input is a number, if it is not a number it will reach the “invalid” state. This is a simple state machine with 9 states. The input is a stream of bytes, initialized to ensure we pass all available states, based on an input that is not available at compile time. The entire input buffer is scanned with this state machine.

### 2.2.3.4 CoreMark Profiling

Since CoreMark contains multiple algorithms, it is interesting to demonstrate how the behavior changes over time. For example, looking at the percentage of control code executed (samples taken at each 1000 cycles) and branch mis-predictions in Figure 2.1, it is obvious where the matrix algorithm is being called. This is portrayed by the low mis- prediction rate and high percentage of control operations, indicative of tight loops (for example, between points 330-390).



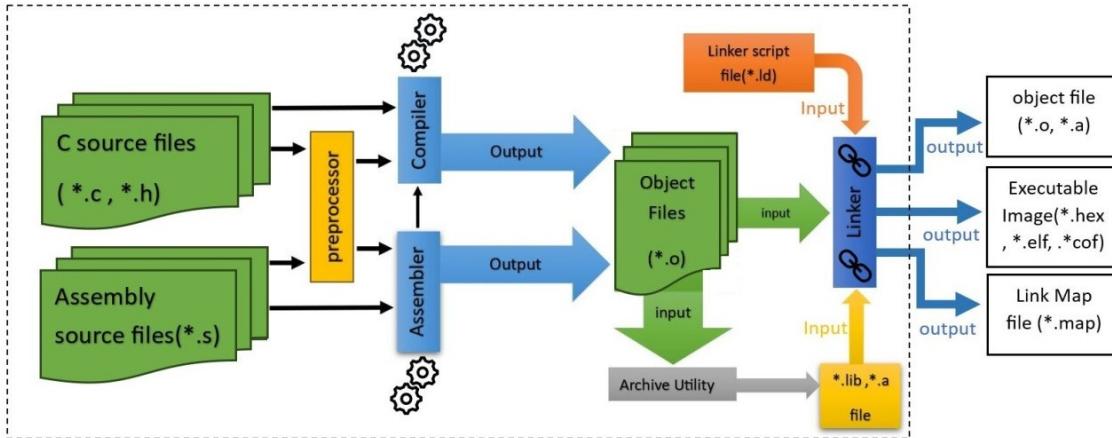
**Figure 2.1:** Distribution of control instructions and mispredictions over CoreMark execution.

Overall CoreMark is well suited to comparing embedded processors. It is small, highly portable, well understood, and highly controlled. CoreMark verifies that all computations were completed correctly during execution, which helps debug any issues that may come up. The run rules are clearly defined and reporting rules are enforced on the CoreMark web site.

## 2.3 C/C++ Build Process

The construction of executable firmware for embedded systems necessitates interventions throughout the compilation toolchain, this requirement is driven by the absence of standardized hardware and resource constraints. Consequently, in our context, the build process is characterized by explicit configuration at each stage, including compiler optimizations, targeted assembly integration, and memory management via linker scripts.

### 2.3.1 Compilation Toolchain



**Figure 2.2:** Compilation Process Diagram

Going from source code in C/C++ to executable firmware involves multiple steps, in this subsection, we will go over them, highlighting the importance of each procedure.

- **Preprocessor :** preprocessing is the first step of the build process, it expands macros and resolves defines as well as stripping comments from the code.
- **Assembler :** The assembler is the part of the toolchain that translates the high-level code into assembly code, which is the human-readable format of machine instruction.
- **Compiler :** Although the we use the term compilation as an equivalent to the whole process, compilation at its core is translating code into machine instructions, this step is what takes assembly mnemonics and turns them into machine code also known as object files.
- **Linker :** The linking stage is the final and most important part of the process, since every c file is compiled separately into its own object file, they are not executable by default, the linker is what declares memory regions and associates symbols to the appropriate sections.

### 2.3.2 Embedded Systems Toolchains

Building applications for embedded systems is quite different from a native build process, although you can create your own cross-compilation toolchain, there are battle-tested toolchains that are available and used across the industry. The most relevant ones being:

- **GCC :** The GCC compiler is an open-source C/C++ compiler, and is part of the GNU utilities, ARM provides their own implementation, prefixed with "arm-none-eabi" and can target most ARM architectures such as ARMv7 and ARMv8.
- **ARM Compiler :** As well as providing a cross-compiling gcc toolchain, ARM has their own compiler based on CLANG and LLVM technologies called ARM compiler.
- **IAR Embedded Workbench:** IAR Systems is a Swedish computer software company that offers development tools for embedded systems. They are known for having a comprehensive development suite and an optimized compiler based on GCC.

### 2.3.3 Build Runners

Whereas simple projects can be compiled directly by invoking the corresponding command via an IDE or a terminal, as the project grows more complex, maintaining dependencies and flags becomes hard; that's where build runners or build system generators come in. They apply a rule-based mechanism to produce the desired output whether it be a library or an executable from its input which is the project's source code. We find two main runners used:

- **Make:** Make is a tool which controls the generation of executables and other non-source files of a program from the program's source files. Make is based on a file named "Makefile" at the top level of the project, it contains the necessary informations describing the build process and how to compute the desired output files.
- **Ninja:** Ninja is a small build system with a focus on speed. It differs from other build systems in two major respects: it is designed to have its input files generated by a higher-level build system, and it is designed to run builds as fast as possible.

### 2.3.4 CMake

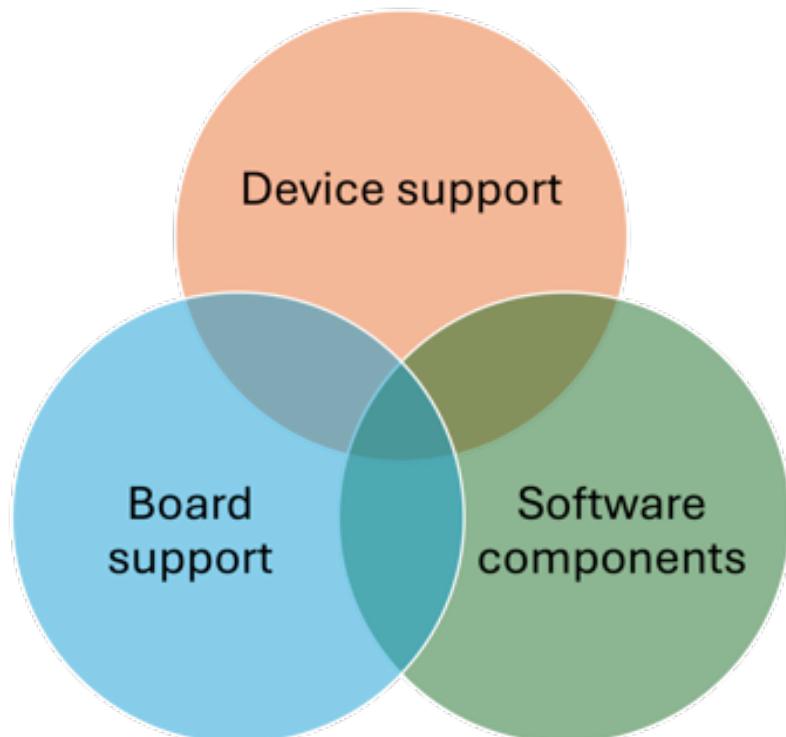
Although build runners alone work in a small scope, they do not provide enough flexibility to work across different environments or have multiple targets. This is the problem that CMake solves; it is a cross-platform build-system generator, that allows your project to run in different contexts without having to write platform specific configuration. It supports dependency management, integrates seamlessly with multiple IDEs and toolchains and offers builtin test and packaging support.

## 2.4 Open-CMSIS-Pack

Software compatibility for component re-use has long been a challenge in the microcontroller space, which is much more diverse at the hardware level compared to PCs or the data center. Open-CMSIS-Pack removes this complexity, delivering a standard for software component packaging and related foundation tools for validation, distribution, integration, management, and maintenance.

### 2.4.1 CMSIS-Packs

CMSIS-Packs are software components that contain device specific startup code, peripheral drivers, middleware, and board support packages. They provide a standardized delivery mechanism for software components and enable consistent project configuration across different development environments.



**Figure 2.3:** Software Packs Types

### 2.4.1.1 CMSIS-Pack Format

The CMSIS-Pack format is used to deliver a software package and is aimed to be scalable for future requirements.

It provides a management process and supports a tool independent distribution for:

- **Device Support :**

- Information about the processor and it's features.
- C and assembly files for the device startup and access to the memory mapped peripheral registers.
- Parameters, technical information, and data sheets about the device family and the specific devices.
- Device description and available peripherals.
- Memory layout of internal and external RAM and ROM address ranges.
- Flash algorithms for programming the device.
- Debug and trace configurations as well as System View Description files for device specific display of the memory mapped peripheral registers.

- **Board Support :**

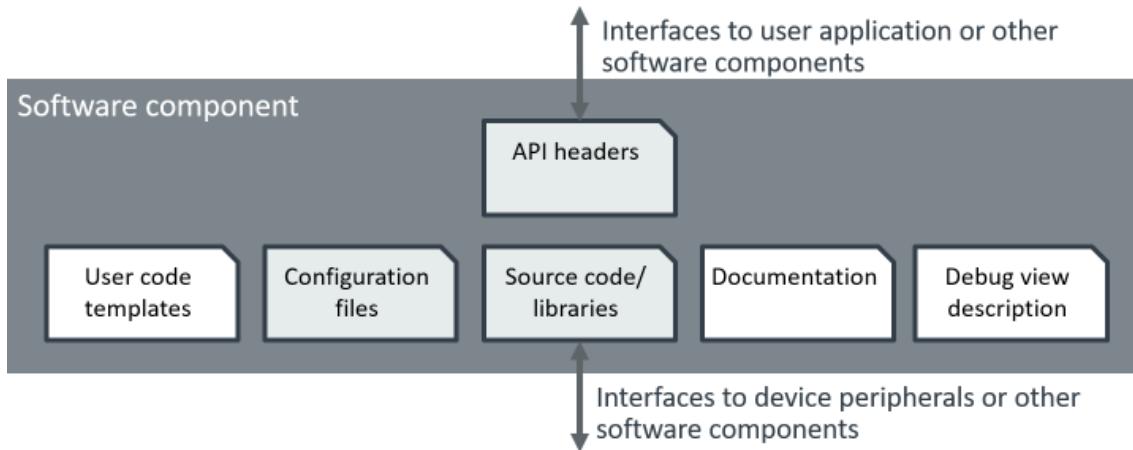
- Information about the development board and it's features.
- Parameters, technical information, and data sheets about the board, the mounted microcontroller, and peripheral devices.
- Drivers for on-board peripheral devices

- **Software components :**

- A collection of source modules, header and configuration files as well as libraries.
- Documentation of the software, including features and APIs.

### 2.4.1.2 Software Components

A software component encapsulates a set of related functions. They can contain C/C++ source files, object code, assembler files, header files, or libraries. The interfaces of software components should be defined with APIs to make them substitutable by other compatible components at design time. CMSIS software components can also refer to multiple interfaces of other software components. This could be also a hardware abstraction layer for a device peripheral. Configuration files contain application specific parameters for a software component. These files are typically copied to the user project workspace; all other files are not modified by the user and can remain in a separate location which avoids that a project workspace is polluted by many source files that should be considered as “black-box” elements by the application programmer.



**Figure 2.4:** Software Component Interface

#### 2.4.1.3 Component classification

A component lists the files that belong to it and that are relevant for a project. The component itself or each individual file may refer to a condition that must resolve to true; if it is false, the component or file is not applicable in the given context.

Each software component must have the following attributes that are used to identify the component:

- **Component Class (Cclass):** A component class which is a top-level component name, for example CMSIS, Device, File System
- **Component Group (Cgroup):** A component group name, for example CMSIS:RTOS, Device:Startup, File System:CORE
- **Component Version (Cversion):** the version number of the software component.

#### 2.4.2 CMSIS-Toolbox

The CMSIS-Toolbox provides command-line tools for project creation and build of embedded applications utilizing CMSIS-Packs. It supports multiple compilation tools. It also helps you with software pack creation, maintenance, and distribution utilizing the CMSIS-Pack format.

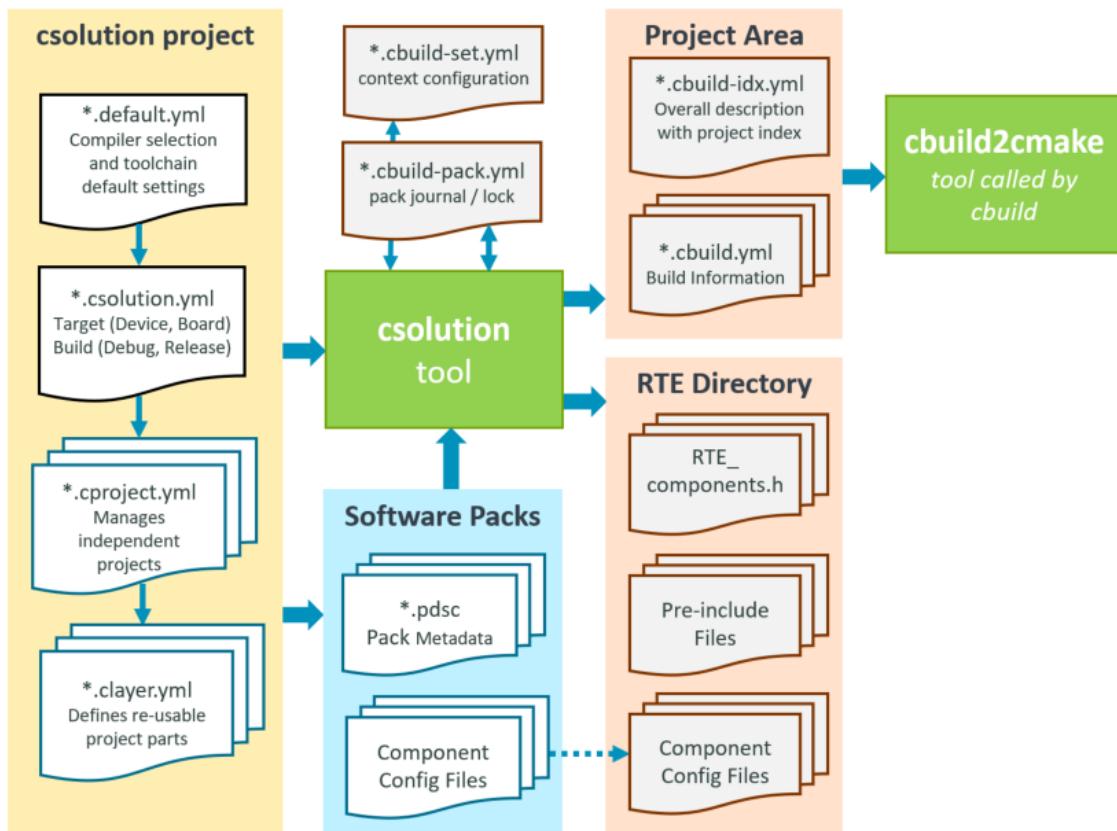
##### 2.4.2.1 Overall Workflow

The CMSIS-Toolbox includes the following tools for the creation of embedded applications:

- **Pack Manager (cpackget):** install and manage software packs in the host development environment.
- **Project Manager (csolution):** create build information for embedded applications that consist of one or more related projects. It performs the following operations:

- **In the Project Area:** Generate build information files \*.cbuild-idx.yml and \*.cbuild.yml with all relevant project information for the build process.
- **In the RTE Directory:**

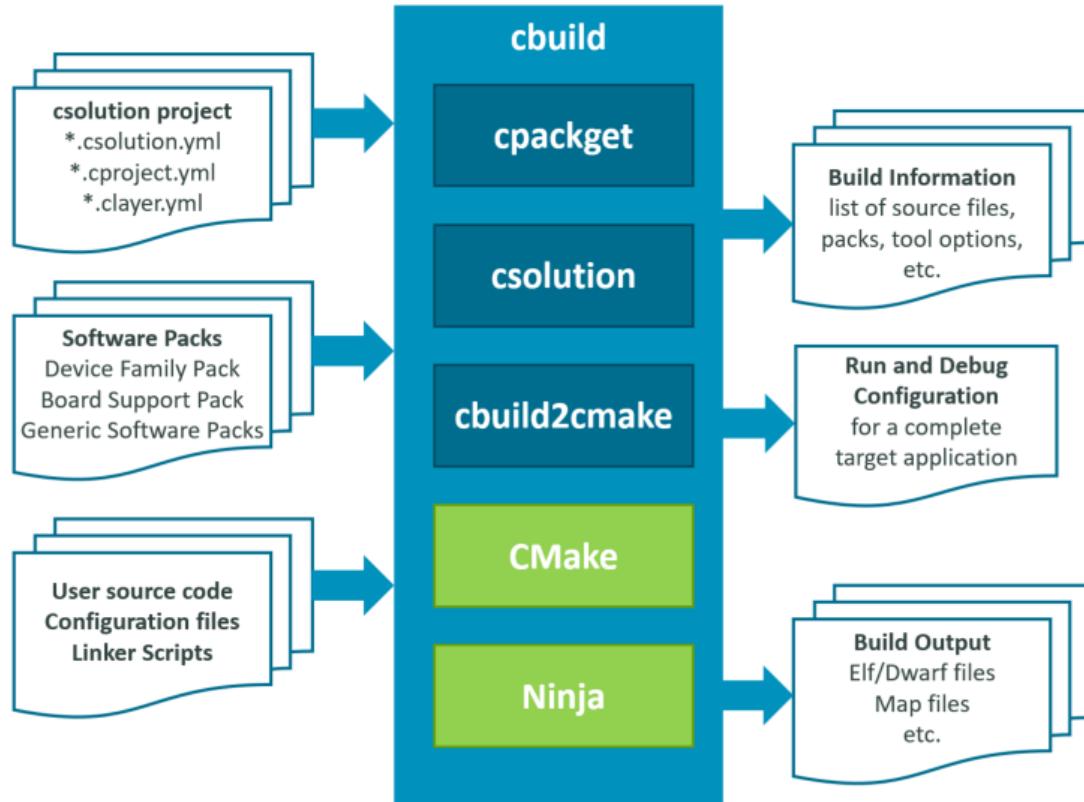
- \* Generate for each context the RTE\_components.h file and pre-include files from the software pack (\*.pdsc) metadata.
- \* Copy the configuration files from selected software components and provide PLM information.



**Figure 2.5:** Csolution Operation

- **Build Invocation (cbuild):** orchestrate the build steps utilizing CMSIS tools and a CMake compilation process. It has two overall modes :
  - **build mode:** generates the application and is the default command.
    - \* When option –packs is used, it downloads missing software packs using cpackget.
    - \* It calls csolution to process the the <name>.csolution.yml project. The output are build information files with all relevant project information for the build process.
  - **setup mode:** generates the setup information for an IDE to populate dialogues, IntelliSense, and project outline views.
    - \* Check YML file syntax against schema for all files specified by \*.csolution.yml.

- \* Check the correctness of all files specified by \*.csolution.yml.



**Figure 2.6:** Cbuild Workflow

#### 2.4.2.2 CMSIS solution files

The CMSIS-Toolbox gets its information from the csolution project files, these are YAML configuration files used to describe the application's context:

- **Solution file** A solution is the software view of the complete system. It combines projects that can be generated independently and therefore, manages related projects. It also specifies the targeted device(s) and build type(s). The file has the format \*.csolution.yml.
- **Project file** The \*.cproject.yml file has the content of a single independent build step, it specifies the source files to compile, sets the include directories and the necessary defines.
- **Layer file** Software layers collect source files and software components along with configuration files for reuse in different projects. Software Layers gives projects a better structure and simplifies:
  - Development flows with evaluation boards and production hardware.
  - Evaluation of middleware and hardware modules across different microcontroller boards.
  - Code reuse across projects, i.e. board support for test-case deployment.

- Test-driven software development on simulation model and hardware.
- **Default Configuration file** The cdefault.yml file contains a common set of compiler-specific settings that select reasonable defaults with miscellaneous controls for each compiler.

### 2.4.2.3 Cbuild2cmake

cbuild2cmake reads the build information files \*.cbuild-idx.yml and \*.cbuild.yml to get all relevant project information for the build process. It generates the output files for CMake build system; describing the overall application build process with the current context configuration, as well as the toolchain specific configuration and source file definitions for groups and software components. CMake is then invoked twice.

- CMake configuration command defines the build generator, source, and build directory with:

```
cmake -G Ninja -S <tmpdir> -B <tmpdir> -Wnodev
```

- CMake build command to build the application program for each context with:

```
cmake --build <tmpdir> -j <n> --target <context>
```

## 2.5 Project Generation

When trying to run benchmarks across a wide variety of MCUs, the project structure follows the same pattern, and the dependencies can be expressed in a logical way relating to the device's metadata. Therefore, automating the process will prove handy since every single step can be automated. There are multiple techniques to be used to generate a fully working project from scratch.

### 2.5.1 Regular Expressions:

The phrase regular expressions, or regexes, is often used to mean the specific, standard textual syntax for representing patterns for matching text. Each character in a regular expression (that is, each character in the string describing its pattern) is either a metacharacter, having a special meaning, or a regular character that has a literal meaning. A regular expression, often called a pattern, specifies a set of strings required for a particular purpose.

#### 2.5.1.1 Operations

Most formalisms provide the following operations to construct regular expressions.

- **Boolean "OR":** A vertical bar separates alternatives. For example, gray|grey can match "gray" or "grey".
- **Grouping** Parentheses are used to define the scope and precedence of the operators (among other uses). For example, gray|grey and gr(a|e)y are equivalent patterns which both describe the set of "gray" or "grey".

- **Quantification** A quantifier after an element (such as a token, character, or group) specifies how many times the preceding element is allowed to repeat. The available quantifications are:
  - **Zero or One:** Denoted by the question mark "?" symbol.
  - **Zero or More:** Denoted by the asterisk "\*" (derived from the Kleene star).
  - **One or More:** Denoted by the plus symbol "+".
  - **N or More:** Denoted by the expression : "{N, }" where N is a positive integer.
  - **N or Less:** Denoted by the expression : "{ ,N}" where N is a positive integer.
  - **Between N and M times:** Denoted by the expression: "{N, M}" where N and M are positive integers such that N < M.
- **Wildcard:** Denoted by the dot "." it matches any single character

These operations can be combined interchangeably to create complex expressions to describe the desired system.

### 2.5.1.2 IEEE POSIX Standard

The IEEE POSIX standard has three sets of compliance: BRE (Basic Regular Expressions), ERE (Extended Regular Expressions), and SRE (Simple Regular Expressions). SRE is deprecated, in favor of BRE, as both provide backward compatibility. BRE and ERE work together. ERE adds ?, +, and |, and it removes the need to escape the metacharacters ( ) and { }, which are required in BRE. Furthermore, as long as the POSIX standard syntax for regexes is adhered to, there can be, and often is, additional syntax to serve specific (yet POSIX compliant) applications. Although POSIX.2 leaves some implementation specifics undefined, BRE and ERE provide a "standard" which has since been adopted as the default syntax of many tools, where the choice of BRE or ERE modes is usually a supported option. Perl regexes have become a de facto standard, having a rich and powerful set of atomic expressions. Perl has no "basic" or "extended" levels. As in POSIX EREs, ( ) and { } are treated as metacharacters unless escaped; other metacharacters are known to be literal or symbolic based on context alone. Additional functionality includes lazy matching, backreferences, named capture groups, and recursive patterns.

## 2.5.2 Templates & File Manipulation

File generation templates are pre-defined structures or blueprints used to create new files with standardized content and formatting.

### 2.5.2.1 Template Definition

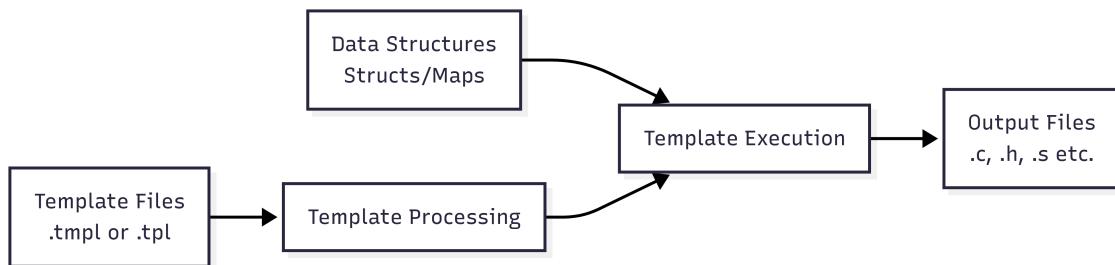
A template file is created containing boilerplate text, placeholders for dynamic content (variables), and sometimes logic for conditional generation.

### 2.5.2.2 Parameterization

The template defines parameters that can be filled in by the user or a program when generating a new file. These parameters can include names, dates, specific values, or other relevant information.

### 2.5.2.3 Template Execution

When a new file is needed, the template is selected, and the required parameters are provided. A generation engine then processes the template, replacing placeholders with the provided values and executing any embedded logic to produce the final file.



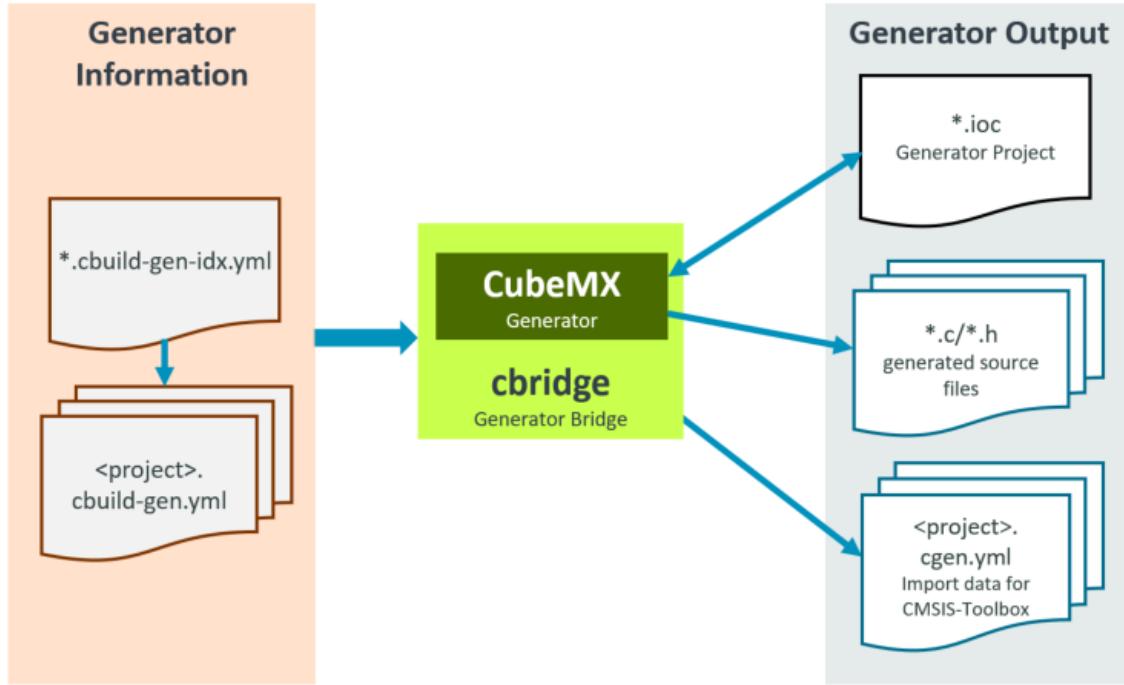
**Figure 2.7:** Templating Process

### 2.5.3 CMSIS-Toolbox Generators

Generators, such as STM32CubeMX or MCUXpresso Config Tools, simplify the configuration for devices and boards. The CMSIS-Toolbox implements a generic interface for generators. They may be used to:

- Configure device and/or board settings, such as clock configuration or pinout.
- Add and configure software drivers, for example, for UART, SPI, or I/O ports.
- Configure parameters of an algorithm, such as DSP filter design or motor control parameters.

### 2.5.3.1 Generator Integration (STM32CubeMX Example)



**Figure 2.8:** Generator Integration in CMSIS-Toolbox

The Figure 2.8 shows how the STM32CubeMX generator is integrated into the CMSIS build process. The data flow is exemplified on STM32CubeMX (Generator ID for this example is CubeMX). The information about the project is delivered to the generator using the Generator Information files (`<solution-name>.cbuild-gen-idx.yml` and `<context>.cbuild-gen.yml`). This information provides CubeMX with the project context, such as the selected board or device, and CPU mode, such as TrustZone, disabled/enabled. The utility cbridge gets as parameter the `<solution-name>.cbuild-gen-idx.yml` and calls the generator. For the CubeMX generator example, these files are created:

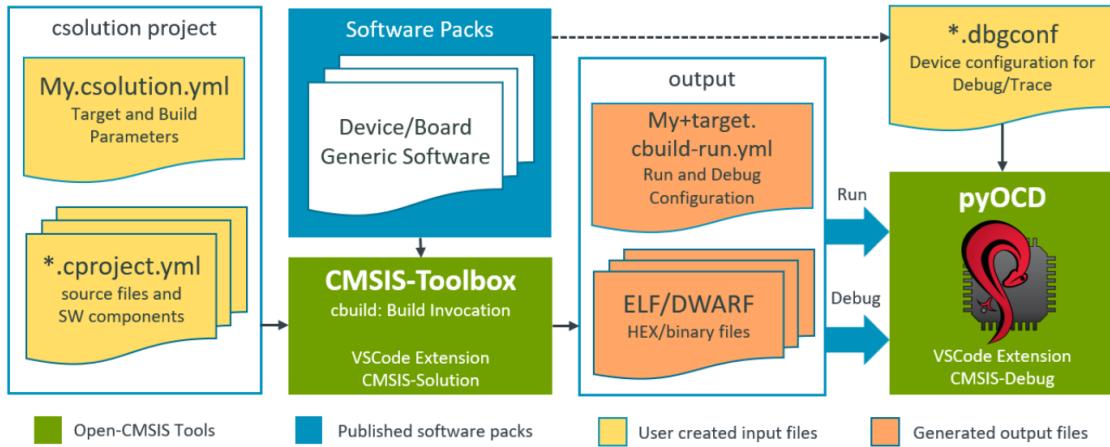
- `*.ioc` CubeMX project file with current project settings
- `*.c/.h` source files, i.e. for interfacing with drivers
- `<project-name>.cgen.yml` (created by cbridge) provides the data for project import into the csolution build process.

## 2.6 Loading And Debugging

Within the context of this project, there are two different approaches to running our application, we will explore both of them providing insight on the advantages of limitations of both.

### 2.6.1 PyOCD

In the ideal usecase, **PyOCD** offers all the needed tools to run and debug our application.



**Figure 2.9:** PyOCD Running and Debugging Workflow

The CMSIS-Toolbox build system manages software packs that contain information about device, board, and software components. It controls the build output (typically ELF/DWARF files), and has provisions for HEX, BIN and post-processing.

### Configuration & Settings

The CMSIS-Toolbox uses the information from the DFP and BSP to simplify the debugger configuration. It generates the file `*.cbuild-run.yml` that contains for one target of a csolution project all information for run and debug. The software packs contain information that is the basis for debug and run settings:

- Flash algorithms of device memory (in DFP) and board memory (in BSP).
- On-board debug adapter (a default programming/debug channel) including features.
- Available memory of device and board.
- Device parameters such as processor core(s) and clock speed.
- Debug Access Sequences and System Description Files that support more complex Cortex-A/R/M configurations.
- Debug Configuration files (`*.dbgconf`) that configure device properties such as trace pins.

- CMSIS-SVD SVD files for viewing device peripherals.
- CMSIS-View SCVD files for analysis of software components (RTOS, Middleware).

### 2.6.2 STM32CubeProgrammer

While more convenient, PyOCD relies on recognizing the connected device in order to perform its operations, while for commercialized devices, this works fine. When working on products that have not been launched, or better yet, still in the pre-production phase, only available as a prototype running on an FPGA, PyOCD no longer can serve its purpose. That's where **STM32CubeProgrammer** comes into play, since the tool is developed within the premises of ST, we are able to load our program into all STM32 MCUs.

## Conclusion

This chapter provided the foundational knowledge required to understand the subsequent work in this report. We began by exploring the STM32 ecosystem, examining the wide range of available microcontrollers, their ARM Cortex-M cores, and critical peripherals such as UART. We also reviewed the STM32Cube firmware package, which streamlines development through standardized libraries like CMSIS, HAL, and LL drivers.

Next, we covered benchmarking principles with a focus on embedded systems. We highlighted the unique challenges of benchmarking microcontrollers, including clock source provisioning, memory mapping, and custom I/O implementations. CoreMark was introduced as a reliable and widely adopted benchmark for evaluating MCU performance in a standardized manner, providing meaningful metrics for comparison.

Afterwards, we discussed the embedded systems build process, emphasizing the importance of toolchains, linking, and memory management. We examined build systems like Make, Ninja, and CMake as a higher-level generator for complex, cross-platform builds.

A key part of this chapter was the introduction of Open-CMSIS-Pack and the CMSIS-Toolbox, which address the complexity of managing device- and board-specific software components. We detailed their role in packaging, versioning, and automating builds.

Finally, we explored project generation techniques, from basic methods like regular expressions and templating to advanced integration with generators like STM32CubeMX.

In summary, this chapter established a comprehensive theoretical framework, connecting concepts of hardware, benchmarking, toolchains, and automation. These concepts form the backbone of the methodology applied in later chapters, ensuring that the processes for benchmarking and project generation are both systematic and scalable.

# OBJECTIVES SPECIFICATION AND WORK ENVIRONMENT

---

## Contents

1	Project Specification . . . . .	29
2	Structural Decisions . . . . .	30
3	Use-Case Diagram . . . . .	32
4	Work Environment . . . . .	34

## Introduction

This chapter will first define the project's functional and non-functional requirements, then we will discuss the chosen structural decisions, explaining the reasoning behind their selection. Finally we will specify the hardware and software resources necessary for this project.

### 3.1 Project Specification

Requirements analysis is a fundamental phase in every project realization process. It is based on the study of the project's features as well as the constraints. In this section, we will cover both the functional and non-functional requirements.

#### 3.1.1 Functional Requirements

The goal of the project is to generate a running CoreMark project on STM32 devices using CMSIS-Toolbox in an automated way. Within this context, this means guaranteeing the following concepts:

**Table 3.1:** Functional Requirements for CMSIS-Toolbox based automated benchmarking

Requirements	Description
<b>Automation</b>	The system must automatically generate a CoreMark benchmarking project for STM32 devices without requiring manual configuration.
<b>Device Adaptability</b>	The generated project must adapt to different STM32 families and configurations.
<b>CoreMark Integration</b>	The CoreMark benchmark must be integrated and ready to run immediately on the target hardware.
<b>Result Reporting</b>	The system must provide a standardized mechanism for reporting benchmark results.
<b>Multi-Toolchain Support</b>	The project must support multiple compilers such as GCC, ARM Compiler, and IAR.

#### 3.1.2 Non-Functional Requirements

Below are the non-functional requirements or the constraints that the functional expectations must abide by:

- **Performance Requirements:**

- **Low Overhead** The project must not add significant, if any overhead besides the CoreMark runtime, this insures the integrity of the benchmarking results.
- **Compiler Optimizations** The project must provide the most optimal compiler configuration to ensure the maximum performance results.

- **Reliability Requirements:**

- **Correctness** The project must be functional and able to run without manual fixes.
- **Consistency** The project must produce consistent results amongst STM32 devices.
- **Error Handling** The project must fail gracefully and generate meaningful error messages.

- **Usability Requirements:**

- **Ease of use** The generation process must be simple and intuitive, the project structure must be clear and consistent.
- **Standardized Output** The results must be presented in a clear format to facilitate further automation and data collection.

## 3.2 Structural Decisions

Before delving further into the implementation details, it is crucial to understand the rationale behind the structural decisions chosen, for both the generation tool and the CoreMark project. This section elucidates the reasons behind the choices and their relevance to the project's objectives.

### 3.2.1 CoreMark Project

The CoreMark project is the end result of the generation tool, it is meant to be runnable out of the box with the 3 main compilers (GCC, ARM, and IAR).

Ensuring the cross-toolchain support is done by providing the necessary compiler specific directives:

- **Linker Scripts** Each compiler has their own unique format for linker scripts:
  - **GCC:** GCC uses the .ld file extension and the LDScript syntax for the linking phase, it is structured in a declarative way to generate regions, sections and describe behavior within elements as well as exporting symbols.
  - **IAR:** IAR uses the .icf file extension as well as proprietary syntax for the linking phase, it allows the user to simply declare regions and optionally sections and takes care of the rest.
  - **ARM:** ARM compiler uses the .sct file extension, you only have to declare memory regions and the rest is handled either in C code or by the compiler directly.
- **Startup Files** The startup file is written in assembly (This approach is changed in HAL2), and although most of the code is common between the 3 compilers, some specific instructions/symbols are different, as well as the libc initialization function is different as each compiler uses a different implementation.

- **Compiler Options** Each compiler has their own set of compiler flags to be used, providing each one with the appropriate configuration is crucial to ensure consistent running.
- **Generic Print Function Implementation** As mentioned prior, each compiler uses a different implementation of libc, meaning that the syscall behind the standard library's printf function are different, providing our own implementation and passing it to CoreMark for result reporting is the most efficient and platform-agnostic solution.

The table 3.2 provides an overview of the architecture of the CoreMark project.

**Table 3.2:** CoreMark Project Structure

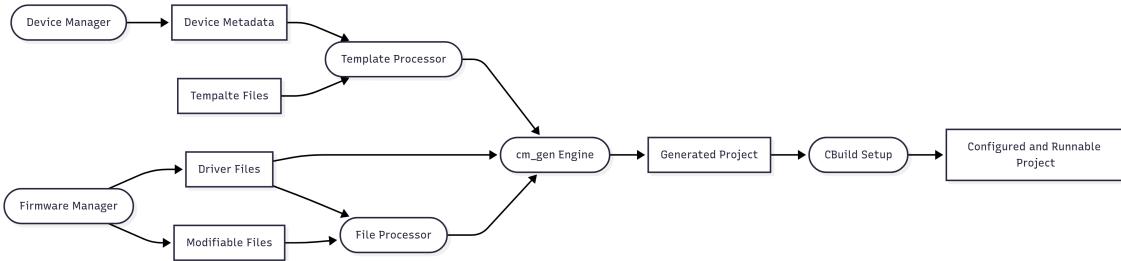
---

Element	Description
<b>User Code</b>	This component provides the definition for the user application's entry point as well as the UART peripheral configuration.
<b>Driver</b>	This component includes the necessary HAL drivers to enable the UART peripheral.
<b>Toolchain_Specific</b>	This component contains the toolchain specific source and header files to modify if the user wants to modify system configurations such as linker scripts and startup files.
<b>CoreMark</b>	This component contains the source code of the CoreMark benchmark to be invoked within the usercode's entry point.
<b>coremark.csolution.yml</b>	This is the workspace file for CMSIS-Toolbox to have knowledge of the project, it defines the DFP, ARM's CORE component, alongside the target device, build types and compiler selection.
<b>coremark.cproject.yml</b>	This is the project description file, it contains the source files to be compiled, user defines for UART functionality and the include paths.
<b>cdefault.yml</b>	This is the file that contains all the compiler options, in our context, the configuration is meant to provide the most performance-oriented setup.

---

### 3.2.2 Project Generation Tool

The architecture of the CoreMark project is quite complex and contains multiple pieces that must be either generated dynamically or fetched from different resources.



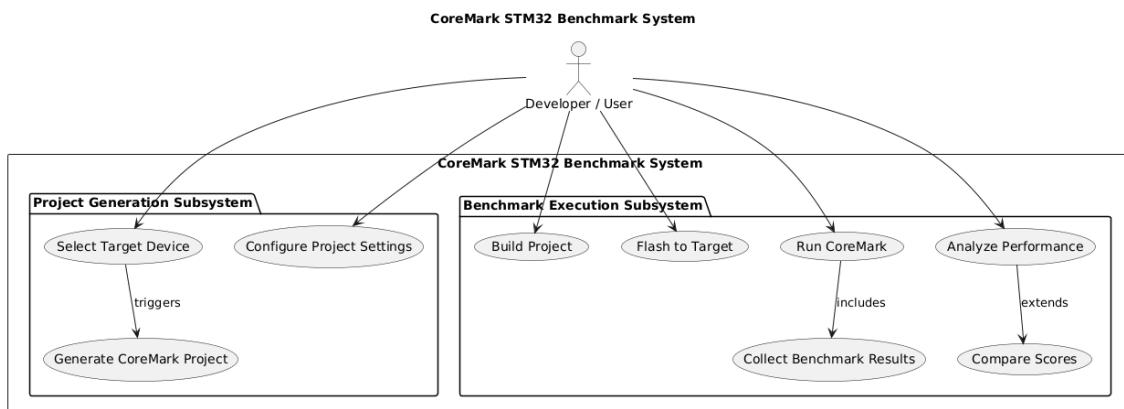
**Figure 3.1:** Project Generation Tool Architecture

The figure 3.1 shows the multiple modules within the project generation tool.

**Table 3.3:** Project Generation Tool Structure

Module	Description
<b>Device Manager</b>	Extracts the device metadata
<b>Firmware Manager</b>	Manages the device's firmware pack and extracting the necessary files
<b>Template Processor</b>	Generates files from the template files and the gathered data
<b>File Processor</b>	Modifies firmware files that cannot be templated to accomodate for our project's context
<b>cm_gen Engine</b>	Orchestrates and runs the different modules

### 3.3 Use-Case Diagram



**Figure 3.2:** Automated CoreMark Benchmarking Use-Case Diagram

The Use-Case diagram in Figure 3.2 illustrates the interactions between a user, the project generation tool and the project's execution space. Refer to Table 3.4 for an in-depth explanation:

**Table 3.4:** Automated CoreMark Benchmarking

Use Case	Relevance
<b>Project Generation Subsystem</b>	
<b>Select Target Device</b>	The developer selects the STM32 device or family for which the CoreMark project should be generated. This ensures that the automation tool generates the correct configuration files and CMSIS device support.
<b>Configure Project Settings</b>	The developer configures CoreMark-specific parameters such as iteration counts, seed values, and compiler optimization flags before building and running the benchmark.
<b>Generate CoreMark Project</b>	The automation tool generates a complete project structure, including the <code>solution</code> files and necessary source code, ready to be built and deployed for the selected STM32 target.
<b>CoreMark Project Subsystem</b>	
<b>Build Project</b>	The CoreMark project is compiled using the CMSIS build system and toolchain to produce a firmware image for the target hardware.
<b>Flash Target</b>	The compiled binary is flashed to the STM32 device to prepare it for execution.
<b>Run CoreMark</b>	The benchmark executes on the STM32 target, performing operations such as list processing, matrix manipulation, and state machine handling to measure CPU performance.
<b>Collect CoreMark Results</b>	During execution, CoreMark outputs the cycle count, execution time, and final score.
<b>Analyze Performance</b>	The developer interprets the CoreMark/MHz score and other performance metrics to determine how well the device performs within the specified context.
<b>Compare Scores</b>	Performance results are compared across different devices, toolchains, or configurations to guide hardware selection or optimization decisions.

## 3.4 Work Environment

In this section, we outline the hardware and software resources utilized during the internship project that were essential for the development testing, and validation.

### 3.4.1 Hardware Resources

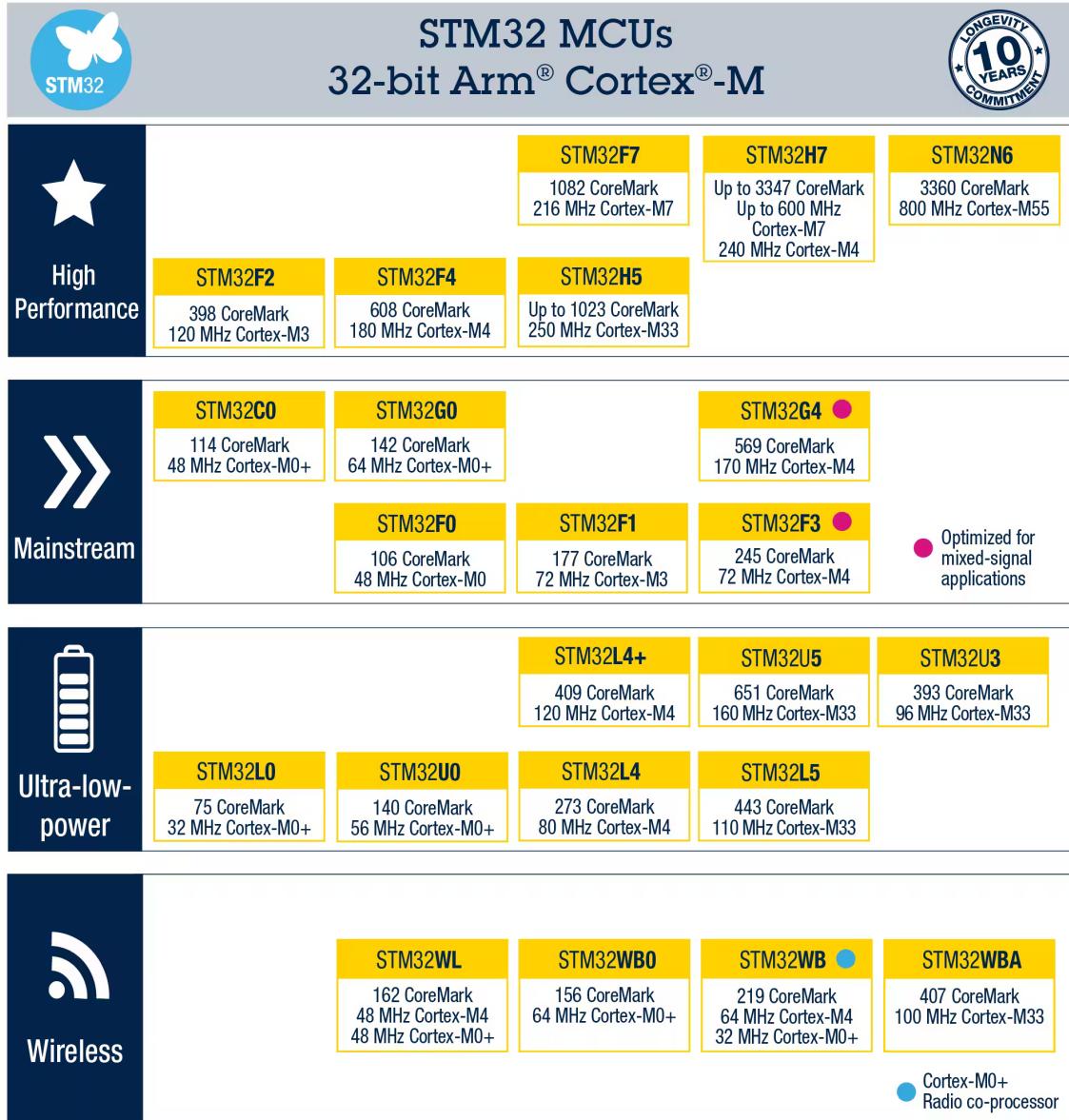


Figure 3.3: STM32 Microcontroller Portfolio

The project is meant to work on all STM32 MCUs, therefore as a base unit, the validation was done on a single board from all STM32 MCU families. Table 3.5 describes all the available families:

**Table 3.5:** STM32 Microcontroller Families

<b>Family</b>	<b>Core</b>	<b>Maximum Frequency(MHz)</b>	<b>Read-Only Memory</b>	<b>Random Access Memory</b>	<b>Additional Features</b>
<b>STM32C0</b>	Arm Cortex-M0+	48MHz	16-256KB	6-36KB	-
<b>STM32F0</b>	Arm Cortex-M0	48MHz	16-256KB	4-32KB	-
<b>STM32F1</b>	Arm Cortex-M3	72MHz	16KB-1MB	4-96KB	-
<b>STM32F2</b>	Arm Cortex-M3	120MHz	128KB-1MB	64KB-128KB	ART Accelerator
<b>STM32F3</b>	Arm Cortex-M4	72MHz	32-512KB	16-80KB	CCM-SRAM and FPU/DFP instructions
<b>STM32F4</b>	Arm Cortex-M4	180MHz	64KB-2MB	32-384KB	Chrom-ART Accelerator
<b>STM32F7</b>	Arm Cortex-M7	216MHz	64K-2MB	256-512KB	L1 Data and Instruction Caches, TCM, Read-While-write Flash capabilities
<b>STM32G0</b>	Arm Cortex-M0+	64MHz	16-512KB	8-144KB	
<b>STM32G4</b>	Arm Cortex-M4	170MHz	32-512KB	32-128KB	CCM-SRAM and FPU/DFP instructions
<b>STM32H5</b>	Arm Cortex-M33	250MHz	128KB-2MB	32-640KB	Integrated Instruction and Data Cache peripherals

Continued on next page

Table 3.5 – Continued from previous page

<b>Family</b>	<b>Core</b>	<b>Maximum Frequency</b>	<b>Read-Only Memory</b>	<b>Random Access Memory</b>	<b>Additional Features</b>
<b>STM32H7</b>	Arm Cortex-M7	600MHz	64KB-2MB	536KB-1.4MB	L1 Data and Instruction Cache, TCM, Chrome-ART and NeoChrom Accelerators.
<b>STM32L0</b>	Arm Cortex-M0+	32MHz	8-192KB	2-20KB	Up to 6KB of EEPROM
<b>STM32L1</b>	Arm Cortex-M3	32MHz	32-512KB	4-80KB	Up to 16KB of EEPROM
<b>STM32L4</b>	Arm Cortex-M4	80MHz	64KB-1MB	40-320KB	Chrom-ART Accelerator
<b>STM32L4+</b>	Arm Cortex-M4	120MHz	512KB-2MB	320-640KB	Chrom-ART Accelerator
<b>STM32L5</b>	Arm Cortex-M33	110MHz	256-512MB	256KB	ART Accelerator
<b>STM32N6</b>	Arm Cortex-M55	800MHz	0	4.2MB	Neural-ART Accelerator(Up to 1GHz Clock Speed)
<b>STM32U0</b>	Arm Cortex-M0+	56MHz	16-256KB	12-40KB	-
<b>STM32U3</b>	Arm Cortex-M33	96MHz	512KB-1MB	256KB	Integrated Instruction and Data Cache peripherals

Continued on next page

Table 3.5 – Continued from previous page

<b>Family</b>	<b>Core</b>	<b>Maximum Frequency</b>	<b>Read-Only Memory</b>	<b>Random Access Memory</b>	<b>Additional Features</b>
<b>STM32U5</b>	Arm Cortex-M33	160MHz	128-4MB	274KB-3MB	Integrated Instruction and Data Cache peripherals
<b>STM32WB</b>	Arm Cortex-M4	64MHz	256KB-1MB	48-256KB	-
<b>STM32WB0</b>	Arm Cortex-M0+	64MHz	192-512KB	24-64KB	-
<b>STM32WBA</b>	Arm Cortex-M33	100MHz	512KB-2MB	64-512KB	Integrated Instruction and Data Cache peripherals
<b>STM32WL</b>	Arm Cortex-M4	64MHz	64-256KB	8-64KB	-

### 3.4.2 Software Resources

The following software tools were used for the development, debugging and testing of the project:

#### Programming Languages

- **C:** C is a general-purpose programming language. By design, C gives the programmer relatively direct access to the features of the typical CPU architecture, customized for the target instruction set. It has been and continues to be used to implement operating systems (especially kernels), device drivers, and protocol stacks, and embedded applications. C is used on computers that range from the largest supercomputers to the smallest microcontrollers.
- **Go:** Go (or Golang) is a high-level general purpose programming language that is statically typed and compiled. It is known for the simplicity of its syntax and the efficiency of development that it enables by the inclusion of a large standard library supplying many needs for common projects.
- **Python:** Python is a high-level, general-purpose programming language. Its design philosophy emphasizes code readability with the use of significant indentation. Python is dynamically type-checked and garbage-collected. It supports multiple programming paradigms, including structured (particularly procedural), object-oriented and functional programming.

## Integrated Development Environments and Text Editors

### 3.4.2.1 Keil µvision

### 3.4.2.2 IAR Embedded Workbench

IAR Embedded Workbench is an integrated development environment (IDE) used for programming, debugging, and optimizing embedded applications. It provides comprehensive support for STM32 microcontrollers. Key features include:

- Advanced debugging capabilities with breakpoints, watch windows, and real-time data visualization.
- Code optimization tools to improve performance and reduce memory footprint.
- Integrated support for STM32CubeMX, allowing seamless project setup and configuration.



**Figure 3.4:** IAR Embedded Workbench

### 3.4.2.3 Visual Studio Code

## Embedded Systems Compiler Toolchains

### 3.4.2.4 GCC

### 3.4.2.5 ARM Compiler v6

### 3.4.2.6 IAR Toolchain

## Development Tools

### 3.4.2.7 CMake

### 3.4.2.8 CMSIS-Toolbox

- **csolution**
- **cproject**
- **cpackage**

### 3.4.2.9 PyOCD

### 3.4.2.10 OpenOCD

### 3.4.2.11 STM32CubeProgrammer

### 3.4.2.12 STM32CubeMX

STM32CubeMX is a graphical software configuration tool that simplifies the development of STM32-based applications. It allows developers to:

- Configure microcontroller peripherals and middleware components through an intuitive graphical interface.
- Generate initialization code for STM32 microcontrollers, reducing development time.
- Integrate with various IDEs, including IAR Embedded Workbench, for a streamlined development workflow.



**Figure 3.5:** STM32CubeMX

## Conclusion

The work environment for this internship includes both hardware and software resources that are essential for the successful implementation of the project.

# SOLUTION IMPLEMENTATION

---

## Contents

1	Demo Overview . . . . .	41
2	Sequence Diagram . . . . .	43
3	Demonstration Details and Explanation . . . . .	44

## Introduction

In this chapter, we provide a detailed step-by-step explanation of the implementation of the "CryptoEngine" demo. This demo showcases the use of cryptographic techniques to establish secure communication between two microcontrollers, specifically the STM32XX and STM32U545 MCUs.

### 4.1 Demo Overview

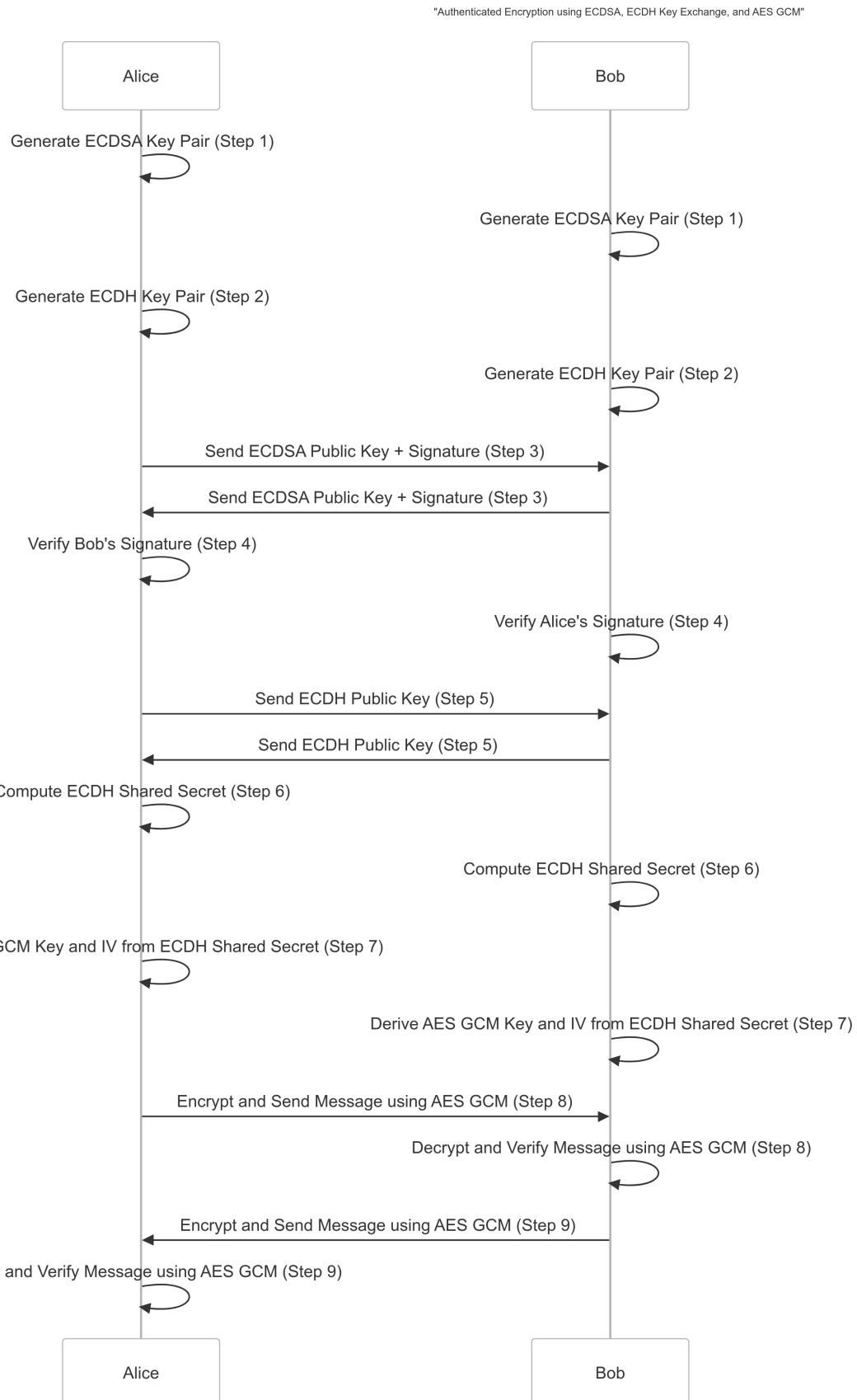
The following section outlines the sequence of operations involved in the "CryptoEngine" demo. The steps are detailed in Table 4.1:

**Table 4.1:** Steps for "CryptoEngine" Demo

Step	Alice	Bob
1	Generate ECDSA Key Pair <i>(ECDSA keys are used for creating and verifying digital signatures)</i>	Generate ECDSA Key Pair
2	Generate ECDH Key Pair <i>(ECDH keys are used for establishing a shared secret)</i>	Generate ECDH Key Pair
3	Send ECDSA Public Key + Signature to Bob	Send ECDSA Public Key + Signature to Alice
4	Verify Bob's Signature using his ECDSA Public Key <i>(Ensures the authenticity of the participants)</i>	Verify Alice's Signature using her ECDSA Public Key
5	Send ECDH Public Key to Bob	Send ECDH Public Key to Alice
6	Compute ECDH Shared Secret using own Private ECDH Key and Bob's Public ECDH Key <i>(Shared secret is used as the basis for deriving encryption keys)</i>	Compute ECDH Shared Secret using own Private ECDH Key and Alice's Public ECDH Key
7	Derive AES GCM Key and IV from ECDH Shared Secret	Derive AES GCM Key and IV from ECDH Shared Secret
8	Encrypt and Send Message using AES GCM	Decrypt and Verify Message using AES GCM
9	Decrypt and Verify Response using AES GCM	Encrypt and Send Response using AES GCM



## 4.2 Sequence Diagram



**Figure 4.1:** Sequence Diagram for "CryptoEngine" Demo

The Sequence Diagram in Figure 4.1 illustrates the process of authenticated encryption using ECDSA for authentication, ECDH for key exchange, and AES GCM for encryption. The diagram shows the interactions between two participants, Alice and Bob, as they perform cryptographic operations to securely exchange messages.

*Note : In our demo, the STM32XX and STM32U545 MCUs will play the roles of Alice and Bob respectively.*

This sequence diagram demonstrates a secure communication process where both participants authenticate each other using ECDSA, establish a shared secret using ECDH, and securely exchange messages using AES GCM. The use of these cryptographic techniques ensures the confidentiality, integrity, and authenticity of the exchanged messages.

## 4.3 Demonstration Details and Explanation

For confidentiality reasons we will only detail the "Bob" side of the demo, since it is using the STM32U545 MCU.

### 4.3.1 ECDSA Key Pair Generation

This is the first step of the demo. It involves setting up PKA peripheral to generate the public ECDSA key.

#### 4.3.1.1 PKA Peripheral Initialization

To compute ECDSA public key we need to set the PKA mode to "ECC Fp scalar multiplication", then we need to input the cryptographic parameters in the correct addresses in PKA RAM.

#### 4.3.1.2 ECC Scalar Multiplication

To input cryptographic parameters in PKA RAM, we need to refer to the STM32U5 reference manual [2] where we can find the specifications for using ECC Fp scalar multiplication. The details of this operation can be found in Figure 4.2.

This figure details the address and size of every cryptography parameter involved in ECC multiplication, which we are using at this level to compute the ECDSA public key. Note that in our demonstration, since we are using a 256-bit curve, the size labeled as EOS (ECC Operand Size) is equal to 320 bits which are 256 bits of actual data and 64 bits of zeros which are necessary when inputting certain data to PKA RAM, as mentioned in the reference manual for U5 [2].

**Table 505. ECC Fp scalar multiplication**

Parameters with direction		Value (note)	Storage	Size
IN	MODE	0x20	PKA_CR	6 bits
IN	Curve prime order $n$ length	(in bits, not null,)	RAM@0x400	64 bits
	Curve modulus $p$ length	(in bits, not null, $8 < \text{value} < 640$ )	RAM@0x408	
	Curve coefficient $a$ sign	– 0x0: positive – 0x1: negative	RAM@0x410	

**Table 505. ECC Fp scalar multiplication (continued)**

Parameters with direction		Value (note)	Storage	Size
IN	Curve coefficient $ a $	(absolute value, $ a  < p$ )	RAM@0x418	EOS
	Curve coefficient $b$	(positive integer)	RAM@0x520	
	Curve modulus value $p$	(odd integer prime, $0 < p < 2^{640}$ )	RAM@0x1088	
	Scalar multiplier $k$	( $0 \leq k < 2^{640}$ )	RAM@0x12A0	
	Point P coordinate $x_P$	( $x < p$ )	RAM@0x578	
	Point P coordinate $y_P$	( $y < p$ )	RAM@0x470	
	Curve prime order $n$	(integer prime)	RAM@0xF88	
OUT	Result: $k \times P$ coordinate $x'$	( $\text{result} < p$ )	RAM@0x578	
	Result: $k \times P$ coordinate $y'$	( $\text{result} < p$ )	RAM@0x5D0	
ERROR	Error $k \times P$	– No errors: 0xD60D – Errors: 0xCBC9	RAM@0x680	64 bits

**Figure 4.2: PKA ECC Fp Scalar Multiplication**

In our case the parameters that we need to use are provided by NIST [3] and are specified in the following table.

**Table 4.2: NIST P-256 Curve Specifications**

Name	Value
Curve Modulus $p$	0xffffffff00000001000000000000000000000000000000ffffffffff
Curve Coefficient $a$	0xffffffff00000001000000000000000000000000000000fffffffffffc
Curve Coefficient $b$	0x5ac635d8aa3a93e7b3ebbd55769886bc651d06b0cc53b0f63bce3c3e27d2604b
Generator Point $G$	(0x6b17d1f2e12c4247f8bce6e563a440f277037d812deb33a0f4a13945d898c296, 0x4fe342e2fe1a7f9b8ee7eb4a7c0f9e162bce33576b315ecccbb6406837bf51f5)
Curve prime order $n$	0xffffffff00000000fffffffffffbce6faada7179e84f3b9cac2fc632551

*Note : These same curve parameters will be reused for ECDSA signature generation and verification as well as ECDH key pair generation.*

These curve specifications have to be put in their specific addresses in PKA RAM in order to set the stage for elliptic curve operations on the P-256 curve.

Figure 4.3 demonstrates the code implementation of the curve parameters.

```
/*Curve Modulus P */
const uint8_t prime256v1_Prime[] = {
    0xff, 0xff, 0xff, 0xff, 0x00, 0x00, 0x00, 0x01, 0x00, 0x00, 0x00, 0x00, 0x00,
    0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00,
    0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00,
    0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00,
};

/*Curve Coefficient a */
const uint8_t prime256v1_A[] = {
    0xff, 0xff, 0xff, 0xff, 0x00, 0x00, 0x00, 0x01, 0x00, 0x00, 0x00, 0x00, 0x00,
    0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00, 0x00,
    0x00, 0x00, 0xfc
};

/*Curve Coefficient b */
const uint8_t prime256v1_B[] = {
    0x5a, 0xc6, 0x35, 0xd8, 0xaa, 0x3a, 0x93, 0xe7, 0xb3, 0xeb, 0xbd, 0x55, 0x76, 0x98, 0x86,
    0xbc, 0x65, 0x1d, 0x06, 0xb0, 0xcc, 0x53, 0xb0, 0xf6, 0x3b, 0xce, 0x3c, 0x3e, 0x27, 0xd2,
    0x60, 0x4b
};

/*Generator G(X,Y) */
uint8_t prime256v1_GeneratorX[] = {
    0x6b, 0x17, 0xd1, 0xf2, 0xe1, 0x2c, 0x42, 0x47, 0xf8, 0xbc, 0xe6, 0xe5, 0x63, 0xa4, 0x40,
    0xf2, 0x77, 0x03, 0x7d, 0x81, 0x2d, 0xeb, 0x33, 0xa0, 0xf4, 0xa1, 0x39, 0x45, 0xd8, 0x98,
    0xc2, 0x96
};

uint8_t prime256v1_GeneratorY[] = {
    0x4f, 0xe3, 0x42, 0xe2, 0xfe, 0x1a, 0x7f, 0x9b, 0x8e, 0xe7, 0xeb, 0x4a, 0x7c, 0x0f, 0x9e,
    0x16, 0x2b, 0xce, 0x33, 0x57, 0x6b, 0x31, 0x5e, 0xce, 0xcb, 0xb6, 0x40, 0x68, 0x37, 0xbf,
    0x51, 0xf5
};

/*Prime Order n */
const uint8_t prime256v1_Order[] = {
    0xff, 0xff, 0xff, 0xff, 0x00, 0x00, 0x00, 0x00, 0x00, 0xff, 0xff, 0xff, 0xff, 0xff, 0xff,
    0xff, 0xff, 0xbc, 0xe6, 0xfa, 0xad, 0xa7, 0x17, 0x9e, 0x84, 0xf3, 0xb9, 0xca, 0xc2, 0xfc,
    0x63, 0x25, 0x51
};
```

**Figure 4.3:** Code Implementation of NIST P-256 Parameters

We will use PKA structures provided by the Hardware Abstraction Layer (HAL) to configure our curve parameters, as illustrated in Figure 4.4. We have developed a function to fill in this structure's members with the NIST P-256 curve parameters as illustrated in Figure 4.5

```
typedef struct
{
    uint32_t scalarMulSize;           /*!< Number of element in scalarMul array */
    uint32_t modulusSize;            /*!< Number of element in modulus, coefA, pointX and pointY arrays */
    uint32_t coefSign;               /*!< Curve coefficient a sign */
    const uint8_t *coefA;             /*!< Pointer to curve coefficient |a| (Array of modulusSize elements) */
    const uint8_t *coefB;             /*!< pointer to curve coefficient b */
    const uint8_t *modulus;            /*!< Pointer to curve modulus value p (Array of modulusSize elements) */
    const uint8_t *pointX;             /*!< Pointer to point P coordinate xP (Array of modulusSize elements) */
    const uint8_t *pointY;             /*!< Pointer to point P coordinate yP (Array of modulusSize elements) */
    const uint8_t *scalarMul;          /*!< Pointer to scalar multiplier k (Array of scalarMulSize elements) */
    const uint8_t *primeOrder;         /*!< pointer to order of the curve */
} PKA_ECCMulInTypeDef;
```

Figure 4.4: HAL PKA ECC Input Structure

```
void Setup_ECC_Input(PKA_ECCMulInTypeDef* ecdh_input_pointer)
{
    ecdh_input_pointer->modulusSize = prime256v1_Prime_len;
    ecdh_input_pointer->coefSign = prime256v1_A_sign;
    ecdh_input_pointer->coefA = prime256v1_absA;
    ecdh_input_pointer->coefB = prime256v1_B;

    ecdh_input_pointer->modulus = prime256v1_Prime;
    ecdh_input_pointer->scalarMulSize = prime256v1_Prime_len;
    ecdh_input_pointer->primeOrder = prime256v1_Order;
}
```

Figure 4.5: PKA ECC Setup

After setting up the elliptic curve parameters, we can generate the ECDSA public key using the ECDSA private key illustrated in Figure 4.6. Figure 4.7 shows the function used to generate the public key, and Figure 4.8 shows the generated key, transmitted through USART to our terminal application. As previously mentioned in ??, the ECDSA public key is a point on the elliptic curve which has a X and Y coordinate, each of them being 256 bits.

```
uint8_t ECDSA_UserKey[32] = {
    0x0f, 0x56, 0xdb, 0x78, 0xca, 0x46, 0x0b, 0x05, 0x5c, 0x50, 0x00, 0x64, 0x82, 0x4b, 0xed, 0x99,
    0x9a, 0x25, 0xaa, 0xf4, 0x8e, 0xbb, 0x51, 0x9a, 0xc2, 0x01, 0x53, 0x7b, 0x85, 0x47, 0x98, 0x13
};
```

Figure 4.6: ECDSA Private Key

```

void pka_ecdsa_generate_publickey(PKA_HandleTypeDef* hpka,
                                    PKA_ECCMulInTypeDef* ecdsa_input_pointer,
                                    uint8_t* ecdsa_private_key,
                                    PKA_ECCMulOutTypeDef* ECDSA_GeneratedPublicKey)
{

    ecdsa_input_pointer->pointX = prime256v1_GeneratorX;
    ecdsa_input_pointer->pointY = prime256v1_GeneratorY;
    ecdsa_input_pointer->scalarMul = ecdsa_private_key;

    if(HAL_PKA_ECCMul(hpka, ecdsa_input_pointer, 5000) != HAL_OK)
    {
        Error_Handler();
    }

    ECDSA_GeneratedPublicKey->ptX = malloc(prime256v1_Prime_len);
    ECDSA_GeneratedPublicKey->ptY = malloc(prime256v1_Prime_len);

    HAL_PKA_ECCMul_GetResult(hpka,ECDSA_GeneratedPublicKey);
}

```

**Figure 4.7:** ECDSA Public Key Generation Function

**ECDSA PubKeyX:**  
 áfÝyÁ&hÛ0ÔÊ><0x8f>wIC,A`DòÒ,Á<0x0b>óÔ<0x01>\*íú<0x8a>  
**ECDSA PubKeyY:**  
 ¿ ``d<0x04>¢éÿæ}GÅ<0x87>ïz<0x97>§ôV,c `Ð,üi(<0x97>:µ±Ë9

**Figure 4.8:** Generated ECDSA Public Key

### 4.3.2 ECDH Key Pair Generation

This is the second step of the demo. Similarly to the previous step, we will use PKA to generate the ECDH public key.

#### 4.3.2.1 ECC Scalar Multiplication

The key generation process using "ECC Fp scalar multiplication" is the same for ECDSA and ECDH, as described in Figure 4.2. We will use the same PKA structure as in ECDSA key generation as illustrated in Figure 4.4.

The ECDH private key illustrated in Figure 4.9 is used along with the function shown in Figure 4.10 in order to generate the ECDH public key, which is shown in Figure 4.11.

```

uint8_t ECDH_UserKey[32] = {
    0x51, 0x9b, 0x42, 0x3d, 0x71, 0x5f, 0x8b, 0x58, 0x1f, 0x4f, 0xa8, 0xee, 0x59, 0xf4, 0x77, 0x1a,
    0x5b, 0x44, 0xc8, 0x13, 0x0b, 0x4e, 0x3e, 0xac, 0xca, 0x54, 0xa5, 0x6d, 0xda, 0x72, 0xb4, 0x64
};

```

**Figure 4.9:** ECDH Private Key

```
void pka_ecdh_generate_publickey(PKA_HandleTypeDef* hpka,
                                  PKA_ECCMulInTypeDef* ecdh_input_pointer,
                                  uint8_t* ecdh_private_key,
                                  PKA_ECCMulOutTypeDef* ECDH_GeneratedPublicKey)
{
    ecdh_input_pointer->pointX = prime256v1_GeneratorX;
    ecdh_input_pointer->pointY = prime256v1_GeneratorY;
    ecdh_input_pointer->scalarMul = ecdh_private_key;

    if(HAL_PKA_ECCMul(hpka, ecdh_input_pointer, 5000) != HAL_OK)
    {
        Error_Handler();
    }

    ECDH_GeneratedPublicKey->ptX = malloc(prime256v1_Prime_len);
    ECDH_GeneratedPublicKey->ptY = malloc(prime256v1_Prime_len);

    HAL_PKA_ECCMul_GetResult(hpka,ECDH_GeneratedPublicKey);
}
```

**Figure 4.10:** ECDH Public Key Generation Function

**ECDH PubKeyX:**  
ECDH PubKeyY:  
F0@<0x14>E<0x88><0x11>u<0x1a><0x1f>U,<0x0e>a<0x13>am.È<0x93>·@NxÜ|Í\`<0x9a>LØ

**Figure 4.11:** Generated ECDH Public Key

### 4.3.3 ECDSA Signature Generation

To generate an ECDSA signature, we will use the PKA mode illustrated in Figure 4.12 [2].

Parameters with direction		Value (note)	Storage	Size
IN	MODE	0x24	PKA_CR	6 bits
	Curve prime order n length ( <i>nlen</i> )	(in bits, not null)	RAM@0x400	64 bits
	Curve modulus p length	(in bits, 8 < value < 640)	RAM@0x408	
	Curve coefficient a sign	0x0: positive 0x1: negative	RAM@0x410	
	Curve coefficient  a	(absolute value, $ a  < p$ )	RAM@0x418	
	Curve coefficient b	(positive integer)	RAM@0x520	
	Curve modulus value p	(odd integer prime, $0 < p < 2^{640}$ )	RAM@0x1088	
	Integer k <sup>(1)</sup>	$(0 \leq k < 2^{640})$	RAM@0x12A0	
	Curve base point G coordinate x	$(x < p)$	RAM@0x578	EOS
	Curve base point G coordinate y	$(y < p)$	RAM@0x470	
	Hash of message z	(hash size equal to <i>nlen</i> ) <sup>(2)</sup>	RAM@0xFE8	
Private key d		$(0 < d)$	RAM@0xF28	
Curve prime order n		(integer prime)	RAM@0xF88	

**Figure 4.12:** ECDSA Sign Operation

We will use the PKA ECDSA signature structure provided by the HAL driver shown in Figure 4.13 along with the function shown in 4.14 to input the signature parameters in PKA RAM.

```
typedef struct
{
    uint32_t primeOrderSize;           /*!< Number of element in primeOrder array */
    uint32_t modulusSize;             /*!< Number of element in modulus array */
    uint32_t coefSign;               /*!< Curve coefficient a sign */
    const uint8_t *coef;              /*!< Pointer to curve coefficient |a|      (Array of modulusSize elements) */
    const uint8_t *coefB;             /*!< Pointer to B coefficient            (Array of modulusSize elements) */
    const uint8_t *modulus;            /*!< Pointer to curve modulus value p   (Array of modulusSize elements) */
    const uint8_t *integer;            /*!< Pointer to random integer k       (Array of primeOrderSize elements) */
    const uint8_t *basePointX;          /*!< Pointer to curve base point xG     (Array of modulusSize elements) */
    const uint8_t *basePointY;          /*!< Pointer to curve base point yG     (Array of modulusSize elements) */
    const uint8_t *hash;               /*!< Pointer to hash of the message     (Array of primeOrderSize elements) */
    const uint8_t *privateKey;          /*!< Pointer to private key d         (Array of primeOrderSize elements) */
    const uint8_t *primeOrder;          /*!< Pointer to order of the curve n   (Array of primeOrderSize elements) */
} PKA_ECDSASignInTypeDef;
```

**Figure 4.13:** HAL PKA ECDSA Input Structure

```
void Setup_ECDSA_Input(PKA_ECDSASignInTypeDef* ecdsa_input_pointer)
{
    ecdsa_input_pointer->primeOrderSize = prime256v1_Order_len;
    ecdsa_input_pointer->modulusSize = prime256v1_Prime_len;
    ecdsa_input_pointer->coefSign = prime256v1_A_sign;
    ecdsa_input_pointer->coef = prime256v1_absA;
    ecdsa_input_pointer->coefB = prime256v1_B;

    ecdsa_input_pointer->modulus = prime256v1_Prime;
    ecdsa_input_pointer->primeOrder = prime256v1_Order;
    ecdsa_input_pointer->basePointX = prime256v1_GeneratorX;
    ecdsa_input_pointer->basePointY = prime256v1_GeneratorY;
}
```

**Figure 4.14:** HAL PKA ECDSA Input Structure

Compared to public key generation, generating the signature requires a new private parameter called "k" which is a 256-bit number only used once to generate the signature. The integer "k" used for this demo is shown in Figure 4.15. The signature generation also uses a hash message, which in our demonstration is pre-shared between the two parties.

```
uint8_t ECDSA_K_Integer[32] = {
    0x94, 0xa1, 0xbb, 0xb1, 0x4b, 0x90, 0x6a, 0x61, 0xa2, 0x80, 0xf2, 0x45, 0xf9, 0xe9, 0x3c, 0x7f,
    0x3b, 0x4a, 0x62, 0x47, 0x82, 0x4f, 0x5d, 0x33, 0xb9, 0x67, 0x07, 0x87, 0x64, 0x2a, 0x68, 0xde
};
```

**Figure 4.15:** ECDSA Integer "K"

After setting up the ECDSA HAL structure, we can launch the ECDSA signing operation using the function shown in Figure 4.16.

```
void pka_ecdsa_generate_signature(PKA_HandleTypeDef* hpka,
                                  PKA_ECDSASignInTypeDef* ecdsa_input_pointer,
                                  uint8_t* ecdsa_private_key,
                                  uint8_t* ECDSA_K_Integer,
                                  uint8_t* hash_msg,
                                  PKA_ECDSASignOutTypeDef* ecdsa_output_pointer)
{
    ecdsa_input_pointer->privateKey = ecdsa_private_key;
    ecdsa_input_pointer->hash = hash_msg;
    ecdsa_input_pointer->integer = ECDSA_K_Integer;

    /* Allocate required space */
    ecdsa_output_pointer->RSign= malloc(prime256v1_Order_len);
    ecdsa_output_pointer->SSign= malloc(prime256v1_Order_len);
    if (ecdsa_output_pointer->RSign== NULL || ecdsa_output_pointer->SSign == NULL)
    {
        /* Not enough memory in heap */
        Error_Handler();
    }
    /* Launch the verification */
    if(HAL_PKA_ECDSASign(hpka, ecdsa_input_pointer, 5000) != HAL_OK)
    {
        Error_Handler();
    }
    HAL_PKA_ECDSASign_GetResult(hpka ,ecdsa_output_pointer, NULL);
}
```

**Figure 4.16:** ECDSA Signing Function

The generated signature is composed of two parts "Signature R" and "Signature S", each being 256 bits long. Figure 4.17 shows the output of the signing operation.

**Signature R:**  
ó¬<0x80>aµ<0x14>y[<0x88>CäÖb<0x95>'í\*ýk<0x1f>jUZZÈ»^oyÈÄ¬  
  
**Signature S:**  
<0x8b>÷x<0x19>È<0x05>{²xlv&+÷7<0x1c>i<0x97>²<0x18>éo<0x17>z<ÍÚ\*Ì<0x05><0x89><0x03>

**Figure 4.17:** Generated ECDSA Signature

#### 4.3.4 ECDSA Public Key and Signature Exchange

After having generated the ECDSA public keys and signatures, the two MCUs exchange these parameters using USART. Exchanging these parameters is crucial for the following step, which is signature verification, to ensure the authenticity of the communication.

Figure 4.18 shows the ECDSA public key and signature received by "Bob" which were generated by "Alice".

```

Received ECDSA Public Key X:
<0x85>$Å<0x02>N-<0x9a>s½èÇ-<0x91>)õxs»<0xad><0x0e>ÐR<0x15>£r„OÛÇ<0x8f>.h
Received ECDSA Public Key Y:
<0x0f>gWj0,âB2ØS<0x0b>RÛL<0x89>ËÅ<0x89>íâ<0x91>ä<0x99>ÝÑ_èp«<0x96>

Received Signature R:
0Âb7ö<0x17>µ<0x81>ÈJ$hÌ<0x8b>Ó<0x0b>±Ëó"þA·<0x88>|à|<0x0e>X<0x84>È

Received Signature S:
`m<0x9f>-<0x8c>Kø5Fy<0x17><0x8f><0x1d>x<0x93>|<0x8d>dèìÅË,%Ë!ÙMg<0x89>

```

**Figure 4.18:** Received ECDSA Signature

### 4.3.5 ECDSA Signature Verification

In this step, each device verifies the ECDSA signature sent by the other party using the PKA mode "ECDSA Verification" shown in Figure 4.19 [2]. A lot of the same curve parameters are the same as ECDSA signature generation , with the addition of the received public key and signature parameters.

	Parameters with direction	Value (note)	Storage	Size
IN	MODE	0x26	PKA_CR	6 bits
	Curve prime order n length ( <i>nlen</i> )	(in bits, not null)	RAM@0x408	64 bits
	Curve modulus p length	(in bits, not null, 8 < value < 640)	RAM@0x4C8	
	Curve coefficient a sign	0x0: positive 0x1: negative	RAM@0x468	
	Curve coefficient  a	(absolute value,  a  < p)	RAM@0x470	
	Curve modulus value p	(odd integer prime, 0 < p < $2^{640}$ )	RAM@0x4D0	
	Curve base point G coordinate x	(x < p)	RAM@0x678	
	Curve base point G coordinate y	(y < p)	RAM@0x6D0	
	Public-key curve point Q coordinate $x_Q$	( $x_Q < p$ )	RAM@0x12F8	
	Public-key curve point Q coordinate $y_Q$	( $y_Q < p$ )	RAM@0x1350	
	Signature part r	(0 < r < n)	RAM@0x10E0	
	Signature part s	(0 < s < n)	RAM@0xC68	
	Hash of message z	(hash size equal to <i>nlen</i> ) <sup>(1)</sup>	RAM@0x13A8	
	Curve prime order n	(integer prime)	RAM@0x1088	EOS

**Figure 4.19:** PKA "ECDSA Verification" Mode

Figure 4.20 shows the code implementation of the ECDSA signature verification process.

```

uint32_t pka_ecdsa_sigVerif(PKA_HandleTypeDef hpka,
                            PKA_ECDSAVerifInTypeDef* inPointer,
                            const uint8_t *PublicKeyCurvePtX,
                            const uint8_t *PublicKeyCurvePtY,
                            const uint8_t *Hash_Msg,
                            const uint8_t *Signature_R,
                            const uint8_t *Signature_S)
{
    /*This function returns 1 when signature is verified, 0 otherwise.
    Set the parameters of ECDSA Signature Verification then verify and check signature validity.*/
    /*Fill in ECDSA Verif Params*/

    inPointer->primeOrderSize = prime256v1_Order_len;
    inPointer->modulusSize = prime256v1_Prime_len;
    inPointer->coefSign = prime256v1_A_sign;
    inPointer->coef = prime256v1_absA;
    inPointer->modulus = prime256v1_Prime;
    inPointer->basePointX = prime256v1_GeneratorX;
    inPointer->basePointY = prime256v1_GeneratorY;
    inPointer->primeOrder = prime256v1_Order;
    inPointer->hash = Hash_Msg; //The sender and receiver have to use the same hash
    inPointer->pPubKeyCurvePtX = PublicKeyCurvePtX; //Received Public Key
    inPointer->pPubKeyCurvePtY = PublicKeyCurvePtY;
    inPointer->RSign = Signature_R;//Received Signature
    inPointer->SSign = Signature_S;

    HAL_PKA_ECDSAVerif(&hpka, inPointer, 5000);
    return HAL_PKA_ECDSAVerif_IsValidSignature(&hpka);
}

```

**Figure 4.20:** ECDSA Verification Function

There are two outcomes to signature verification. Figure 4.21 shows the output of a successful signature verification process, which allows to go on to establish ECDH key exchange, while Figure 4.22 shows the output of a failed signature verification which abruptly ends the communication.

```

Received Signature R:
xÅb7ö<0x17>µ<0x81>ÈJ$hÌ<0x8b>Ó<0x0b>±Ëó"þA.<0x88>|à|<0x0e>X<0x84>È

Received Signature S:
`m<0x9f>-<0x8c>Kø5Fÿ<0x17><0x8f><0x1d>x<0x93>|<0x8d>dèìÅË.%Ë!ÙMg<0x89>

Signature verified successfully!

Waiting to receive ECDH public Key...
-->

```

**Figure 4.21:** Successful ECDSA Signature Verification

```

Received Signature R:
0Âb7ö<0x17>µ<0x81>ÈJ$hÌ<0x8b>Ó<0x0b>±Ëó"þA·<0x88>|à|<0x0e>X<0x84>È

Received Signature S:
`m<0x9f>-<0x8c>Kø5Fÿ<0x17><0x8f><0x1d>x<0x93>|<0x8d>dèìÅË,%Ë!ÙMg<0x89>

Signature Verification Failed !

```

**Figure 4.22:** Failed ECDSA Signature Verification

### 4.3.6 ECDH Public Key Exchange

Now that the two parties have verified each other's signature, we can proceed knowing that authenticity has been assured. The next step is to establish a shared secret which will serve as a basis for establishing a symmetric encryption key. For that, the two devices must exchange the ECDH public keys generated at the start of the demo via USART. Figure 4.23 shows the terminal output of the ECDH public key reception process.

```

Waiting to receive ECDH public Key...
-->

Received ECDH Public Key X:
2/<0x80>7<0x1b>öàD%I9<0x1d><0x97>ÁqJ,<0x7f><0x99><0x0b><0x94><0x9b>ÁxË|c·À-<0x89>á

Received ECDH Public Key Y:
<<0x15>ÓJ\À¹δ<0x9d>èE~<0x87>>³þ±üëT°²<0x95>Ù`P)O®<0x7f>Ù<0x99>

```

**Figure 4.23:** Received ECDH Public Key

### 4.3.7 ECDH Shared Secret Generation

Having exchanged the ECDH public keys, each device will independently calculate the ECDH shared secret which will be a point on the elliptic curve. This point is obtained through multiplying the device's own ECDH private key with the received ECDH public key. Naturally, both devices should obtain the same common 512-bit shared secret.

Shared secret generation is done through ECC scalar multiplication, meaning we will use the PKA mode "ECC Fp scalar multiplication" which has been detailed in Figure 4.2 [2].

Figure 4.24 illustrates the code implementation of ECDH shared secret generation, and Figure 4.25 shows the output result of this operation.

```

void pka_ecdh_generate_shared_secret(PKA_HandleTypeDef* hpka,
                                     PKA_ECCMulInTypeDef* ecdh_input_pointer,
                                     PKA_ECCMulOutTypeDef* ECDH_ReceivedPublicKey,
                                     uint8_t* ecdh_private_key,
                                     PKA_ECCMulOutTypeDef* ECDH_SharedSecret)
{
    uint8_t ECDH_Received_X[32]={0};
    uint8_t ECDH_Received_Y[32]={0};
    uint8_t ECDH_PrivKey[32]={0};

    ecdh_input_pointer->pointX = (uint8_t *)ECDH_Received_X;
    ecdh_input_pointer->pointY = (uint8_t *)ECDH_Received_Y;
    ecdh_input_pointer->scalarMul = (uint8_t *)ECDH_PrivKey;

    if(HAL_PKA_ECCMul(hpka, ecdh_input_pointer, 5000) != HAL_OK)
    {
        Error_Handler();
    }
    ECDH_SharedSecret->ptX = malloc(prime256v1_Prime_len);
    ECDH_SharedSecret->ptY = malloc(prime256v1_Prime_len);

    HAL_PKA_ECCMul_GetResult(hpka,ECDH_SharedSecret);
}

```

**Figure 4.24:** ECDH Shared Secret Generation Function

```

ECDH Shared Secret X:
Qü<0x9d>-RÔ!ç4HJ<0x01><0x8b>|¢ø<0x95>Â<0x92><0x9b>gTf<0xa0>2$Ðzæ<0x11>fÎ
ECDH Shared Secret Y:
G7Ù<0x96><n=$<0x7f>,<0x8d><0x19>ùºÆgÊÇþ<0x12><0x83><0x7f>Ù,<0x8c>fñ<<0x14>ÊÑ

```

**Figure 4.25:** ECDH Shared Secret

#### 4.3.8 AES GCM Key and IV Derivation

Having established the shared secret, we will now derive from it the symmetric encryption key as well as the initialization vector which are needed for AES GCM . Usually, this process would involve a key derivation function and the use of complicated algorithms, but for the purposes of the simplicity of the demo we opted to take the X coordinate of the ECDH shared secret as the 256-bit AES Key and the first 96 bits of the Y coordinate as the initialization vector.

### 4.3.9 AES GCM Symmetric Encryption

For this step, we will use the AES peripheral structure provided by the HAL driver provided in Figure 4.26. We will initialize the peripheral's structure as shown in Figure 4.27, where we select a 256-bit key size and AES GCM mode.

```

typedef struct
{
    uint32_t DataType;           /*!< 32-bit data, 16-bit data, 8-bit data or 1-bit string.
                                    This parameter can be a value of @ref CRYP_Data_Type */
    uint32_t KeySize;           /*!< Used only in AES mode : 128, 192 or 256 bit key length in CRYP1.
                                    128 or 256 bit key length in TinyAES This parameter can be a value
                                    of @ref CRYP_Key_Size */
    uint32_t *pKey;              /*!< The key used for encryption/decryption */
    uint32_t *pInitVect;         /*!< The initialization vector used also as initialization
                                    counter in CTR mode */
    uint32_t Algorithm;          /*!< DES/ TDES Algorithm ECB/CBC
                                    AES Algorithm ECB/CBC/CTR/GCM or CCM
                                    This parameter can be a value of @ref CRYP_Algorithm_Mode */
    uint32_t *Header;            /*!< used only in AES GCM and CCM Algorithm for authentication,
                                    GCM : also known as Additional Authentication Data
                                    CCM : named B1 composed of the associated data length and Associated Data. */
    uint32_t HeaderSize;         /*!< The size of header buffer */
    uint32_t *B0;                /*!< B0 is first authentication block used only in AES CCM mode */
    uint32_t DataWidthUnit;      /*!< Payload Data Width Unit, this parameter can be value of @ref CRYP_Data_Width_Unit */
    uint32_t HeaderWidthUnit;    /*!< Header Width Unit, this parameter can be value of @ref CRYP_Header_Width_Unit */
    uint32_t KeyIVConfigSkip;    /*!< CRYP peripheral Key and IV configuration skip, to config Key and Initialization
                                    Vector only once and to skip configuration for consecutive processings.
                                    This parameter can be a value of @ref CRYP_Configuration_Skip */
    uint32_t KeyMode;             /*!< Key mode selection, this parameter can be value of @ref CRYP_Key_Mode */
    uint32_t KeySelect;           /*!< Only for SAES : Key selection, this parameter can be value of @ref CRYP_Key_Select */
    uint32_t KeyProtection;       /*!< Only for SAES : Key protection, this parameter can be value of @ref CRYP_Key_Protection */
} CRYP_ConfigTypeDef;

```

**Figure 4.26:** AES HAL Structure

```

static void AES_GCM_Init(void)
{
    hcryp_aes.Instance = AES;
    hcryp_aes.Init.DataType = CRYP_NO_SWAP;
    hcryp_aes.Init.KeySize = CRYP_KEYSIZE_256B;
    hcryp_aes.Init.pInitVect = (uint32_t *)pInitVectAES;
    hcryp_aes.Init.Algorithm = CRYP_AES_GCM_GMAC

    hcryp_aes.Init.HeaderSize = 0;

    hcryp_aes.Init.DataWidthUnit = CRYP_DATAWIDTHUNIT_WORD;

    if (HAL_CRYP_Init(&hcryp_aes) != HAL_OK)
    {
        Error_Handler();
    }
}

```

**Figure 4.27:** AES Structure Initialization

All that is left is to derive the AES key and initialization vector from the ECDH shared secret as shown in Figure 4.28.

```
//Format ECDH Shared Secret to 32 Bit for use as symmetric AES key.  
format_Buffer_8to32(ECDH_Shared_Secret.ptX,32,AES_Symmetric_Key,8);  
  
//Take a part of ECDH secret to use as IV  
format_Buffer_8to32(ECDH_Shared_Secret.ptY,32,AES_IV_Source,8);  
  
Create_AES_IV(AES_IV_Source,AES_IV);  
  
/* Get the AES parameters */  
HAL_CRYP_GetConfig(&hcryp_aes, &Conf);  
  
/*AES GCM Configuration*/  
Conf.pKey      = AES_Symmetric_Key;  
Conf.pInitVect = AES_IV;  
HAL_CRYP_SetConfig(&hcryp_aes, &Conf);
```

**Figure 4.28:** AES GCM Key and Initialization Vector Derivation

On the "Bob" side, we will encrypt and send the message "This is Bob" along with the tag that will help in verifying the integrity of the message. Figure 4.29 demonstrates the plaintext, ciphertext and tag generated by the encryption process. Note that the "%" symbol was added for extra padding since the AES peripheral expects a 128-bit input.

```
Plaintext Message :  
This is Bob%%%  
  
Ciphertext Message:  
Ù¥§2<0x81><0x17>ô<0x8b>K<0x8d>ØÁ}®r.uk?ön  
  
Encrypt Tag:  
/ÃÏøÍÔ<0x86>k<0x1d>tä[<0x07>Ó3^-Fg.<0x08><0x88>
```

**Figure 4.29:** AES GCM Key and Initialization Vector Derivation

#### 4.3.10 Message Decryption and Tag Verification

The two devices exchange the encrypted messages and the generated tags. They must now decrypt the message while regenerating a tag. If the received tag is the same as the generated decryption tag, that means the message has been decrypted successfully. Figure 4.30 shows the decryption process on the "Bob" side which shows the correct decryption of the "Alice" message ("This is Alice").

```
Received Tag:  
éç<0x95>xØ<0x98><0x8b><0x16><0x8e>ßñ“³JÍ<0x1f>í6q  
  
Decrypted Text:  
"This is Alice%%"  
  
Generated Tag:  
éç<0x95>xØ<0x98><0x8b><0x16><0x8e>ßñ“³JÍ<0x1f>í6q  
  
Decrypt Tag matches Received Tag .  
  
End of Demo.
```

**Figure 4.30:** Message Decryption Output

The matching of the tags proves that the message was transmitted correctly and without any manipulation. It also ensures that the two sides have managed to derive the exact same symmetric key from the shared secret generation process, meaning that a secure line of communication has been successfully established between the two devices.

## Conclusion

This chapter provided a comprehensive review of the implementation steps for the "CryptoEngine" demo, which demonstrates secure communication between two microcontrollers using cryptographic techniques. We explored the generation and exchange of cryptographic keys, including ECDSA and ECDH keys, and the processes of signature generation, verification, and secure message exchange using AES GCM. We also included relevant code snippets and expected outputs for each step of the demonstration to provide a complete overview.

# Bibliography

- [1] STMicroelectronics, “St company presentation,” 2024, [Accessed 7 February 2024]. [Online]. Available: [https://www.st.com/resource/en/company\\_presentation/company\\_presentation.pdf](https://www.st.com/resource/en/company_presentation/company_presentation.pdf).
- [2] STMicroelectronics, “Rm0456 stm32u5 series arm®-based 32-bit mcus,” 2024, [Accessed 8 February 2024]. [Online]. Available: [https://www.st.com/resource/en/reference\\_manual/rm0456-stm32u5-series-armbased-32bit-mcus-stmicroelectronics.pdf](https://www.st.com/resource/en/reference_manual/rm0456-stm32u5-series-armbased-32bit-mcus-stmicroelectronics.pdf).
- [3] J. Jancar, “Standard curve database,” 2020, [Accessed 17 June 2024]. [Online]. Available: <https://neuromancer.sk/std/nist/P-256>.
- [4] STMicroelectronics, “Stm32 mooc part 3: security features,” 2020, [Accessed 13 February 2024]. [Online]. Available: [https://www.st.com/content/st\\_com/en/support/learning/stm32-education/stm32-moocs/STM32\\_security\\_features](https://www.st.com/content/st_com/en/support/learning/stm32-education/stm32-moocs/STM32_security_features).
- [5] STMicroelectronics, “Stm32 mooc part 2:cryptography basics,” 2020, [Accessed 12 February 2024]. [Online]. Available: [https://www.st.com/content/st\\_com/en/support/learning/stm32-education/stm32-moocs/STM32\\_security\\_features](https://www.st.com/content/st_com/en/support/learning/stm32-education/stm32-moocs/STM32_security_features).
- [6] STMicroelectronics, “St application note 5156 : introduction to security for stm32 mcus,” 2018, [Accessed 27 February 2024]. [Online]. Available: [https://www.st.com/resource/en/application\\_note/an5156-introduction-to-security-for-stm32-mcus-stmicroelectronics](https://www.st.com/resource/en/application_note/an5156-introduction-to-security-for-stm32-mcus-stmicroelectronics).
- [7] D. A.Popovic, “Understanding blockchain for insurance use cases,” 2020, [Accessed 1 July 2024]. [Online]. Available: [https://www.researchgate.net/publication/342136274\\_Understanding\\_blockchain\\_for\\_insurance\\_use\\_cases](https://www.researchgate.net/publication/342136274_Understanding_blockchain_for_insurance_use_cases).
- [8] D. Warburton, “The 2021 tls telemetry report,” 2021, [Accessed 7 March 2024]. [Online]. Available: <https://www.f5.com/labs/articles/threat-intelligence/the-2021-tls-telemetry-report>.
- [9] N. I. of Standards and Technologies, “Recommendations for discrete logarithm-based cryptography: elliptic curve domain parameters,” 2023, [Accessed 24 July 2024]. [Online]. Available: <https://nvlpubs.nist.gov/nistpubs/SpecialPublications/NIST.SP.800-186.pdf>.

# Annexes

## Annexe 1. Exemple d'annexe

Les chapitres doivent présenter l'essentiel du travail. Certaines informations-trop détaillées ou constituant un complément d'information pour toute personne qui désire mieux comprendre ou refaire une expérience décrite dans le document- peuvent être mises au niveau des annexes. Les annexes, **placées après la bibliographie**, doivent donc être numérotées avec des titres (Annexe1, Annexe2, etc.).

Le tableau annexe 1.1 présente un exemple d'un tableau dans l'annexe.

**Tableau annexe 1.1:** Exemple tableau dans l'annexe

0	0
1	1
2	2
3	3
4	4

## Annexe 2. Entreprise

La figure annexe 2.1 présente le logo entreprise.



**Figure annexe 2.1:** Logo d'entreprise

## **Abstract**

This report describes the work carried out during my summer internship at STMicroelectronics, focused on platform-agnostic benchmarking. The main objective was to run Coremark on STM32 devices using Csolution project structure. To achieve this, I put to use my knowledge in software and embedded development, C code compilation and code generation, using tools such as CMSIS-Toolbox, C and Golang. The results helped to drastically reduce the time required to setup and run Coremark projects using multiple compilers, as well as generating the most optimal results. This internship also allowed me to strengthen my skills in the compilation process, embedded projects architecture design and gain insight into the specific challenges of embedded systems engineering.

**Keywords :** C/C++, Golang, Embedded Systems, STM32, Compilation, Code Generation.

## **Résumé**

Ce rapport décrit les travaux réalisés lors de mon stage d'été chez STMicroelectronics, axé sur l'analyse comparative indépendante de la plateforme. L'objectif principal était d'exécuter Coremark sur des microcontrôleurs STM32 en utilisant la structure de projet Csolution. Pour ce faire, j'ai mis à profit mes connaissances en développement logiciel et embarqué, en compilation et génération de code C, à l'aide d'outils tels que CMSIS-Toolbox, C et Golang. Les résultats ont permis de réduire considérablement le temps nécessaire à la configuration et à l'exécution des projets Coremark avec plusieurs compilateurs, tout en optimisant les résultats. Ce stage m'a également permis de renforcer mes compétences en compilation, en conception d'architecture de projets embarqués et de mieux comprendre les défis spécifiques de l'ingénierie des systèmes embarqués.

**Mots clés :** C/C++, Golang, Systèmes embarqués, STM32, Compilation, Génération de Code.